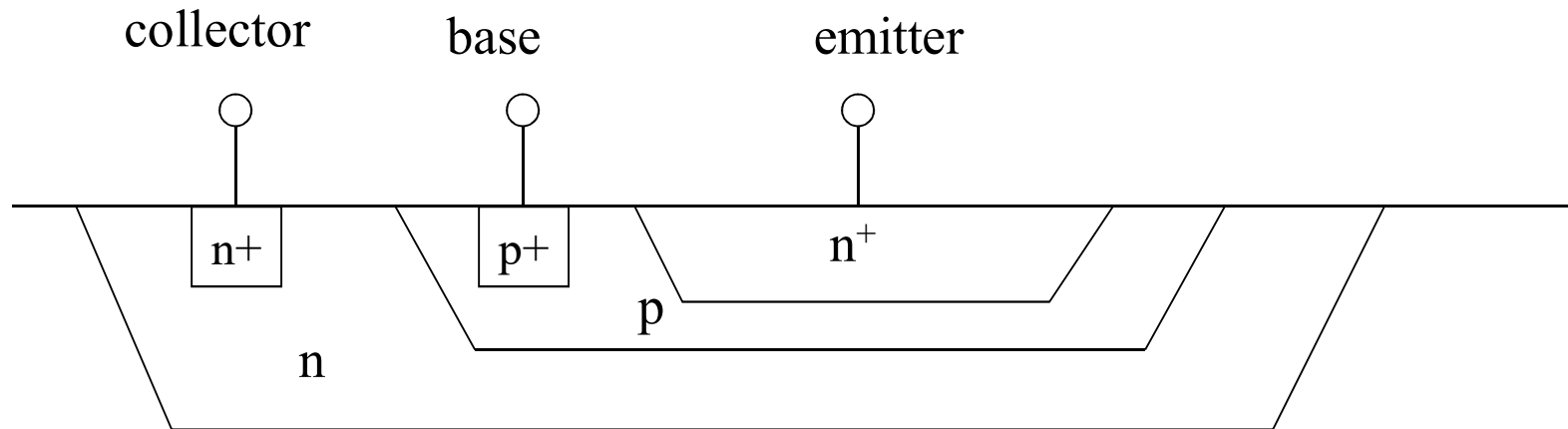


Bipolar transistors

bipolar transistors

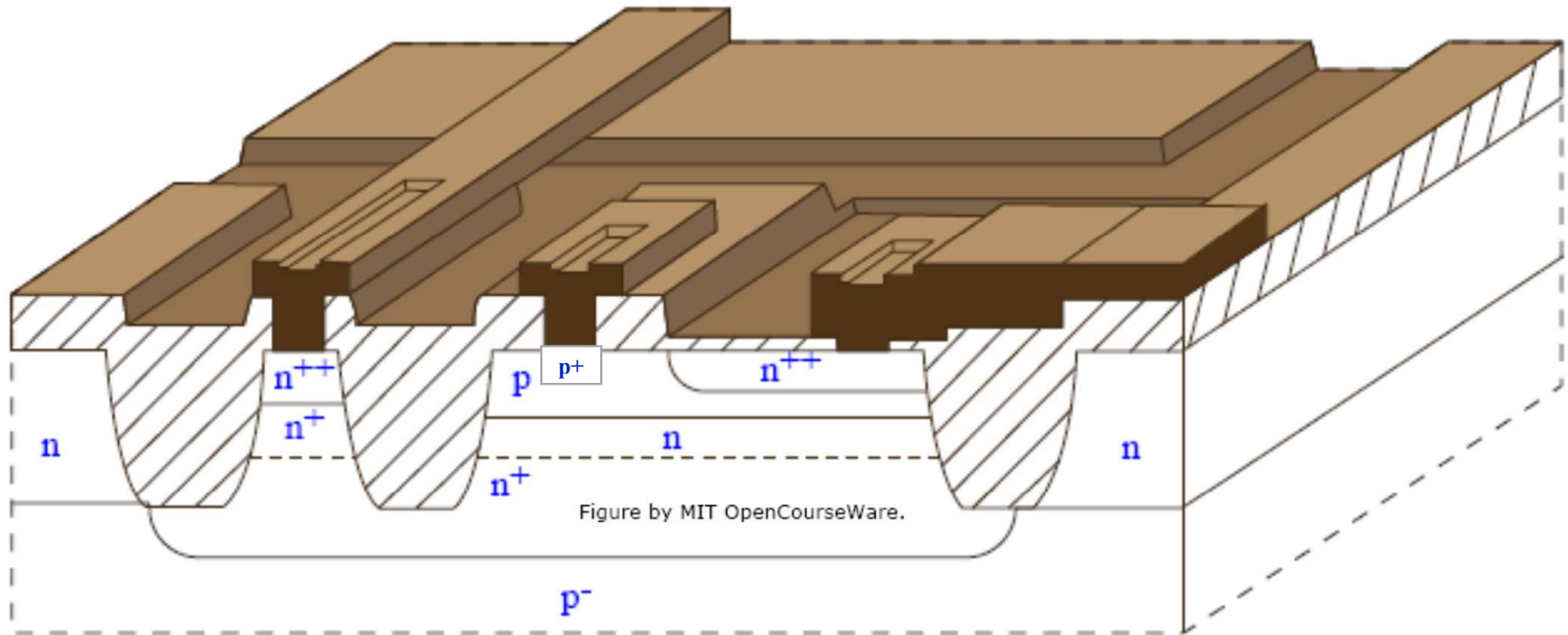
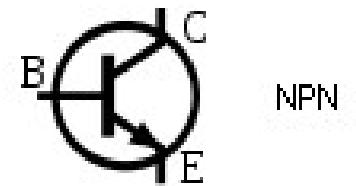
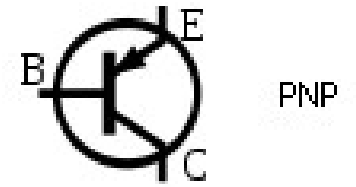
npn transistor



lightly doped p substrate

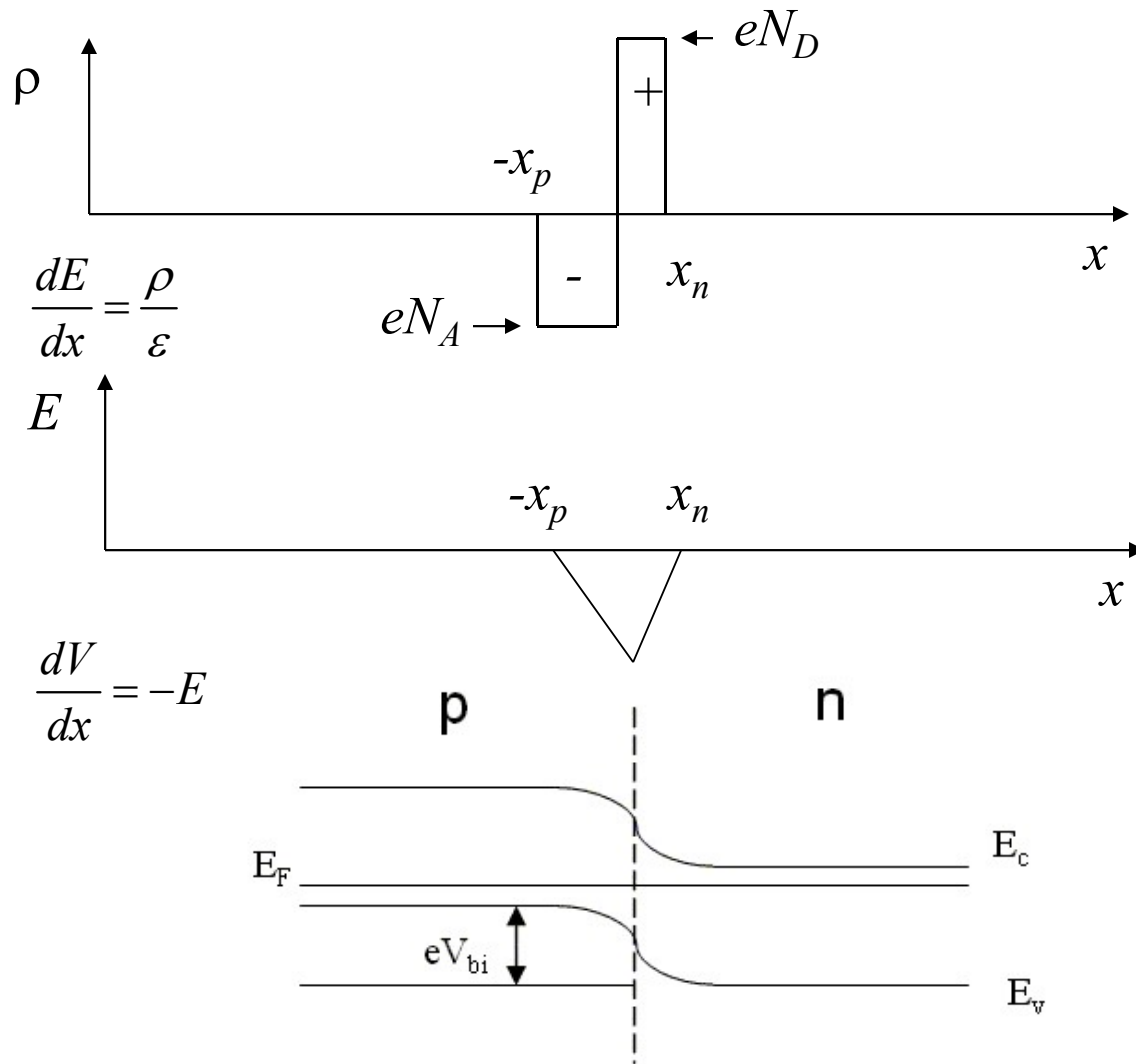
Used in front-end high-frequency receivers (mobile telephones).

bipolar transistors



Oxide isolated integrated BJT - a modern process

abrupt junction



$$eV_{bi} = k_B T \ln \left(\frac{N_D N_A}{n_i^2} \right)$$

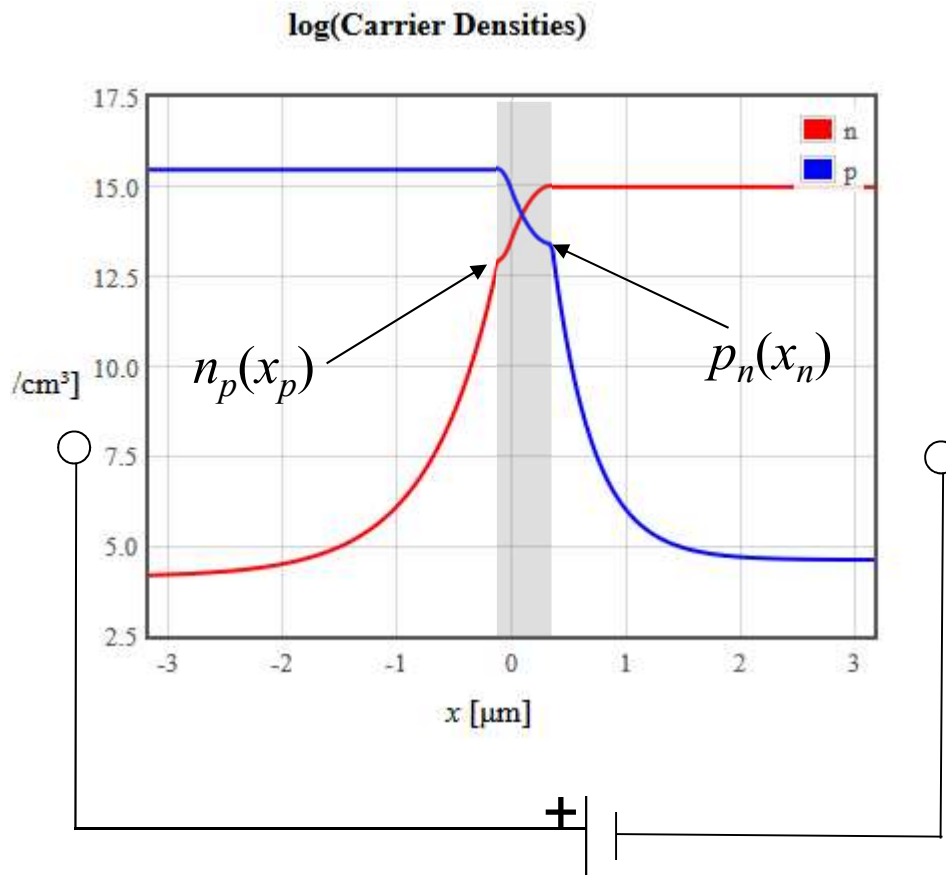
$$E = -\frac{eN_A}{\epsilon} (x + x_p) \quad -x_p > x > 0$$

$$E = \frac{eN_D}{\epsilon} (x - x_n) \quad 0 > x > x_n$$

$$V = \frac{eN_A}{\epsilon} \left(\frac{x^2}{2} + xx_p \right) \quad -x_p > x > 0$$

$$V = \frac{-eN_D}{\epsilon} \left(\frac{x^2}{2} - xx_n \right) \quad 0 > x > x_n$$

Forward bias, $V > 0$



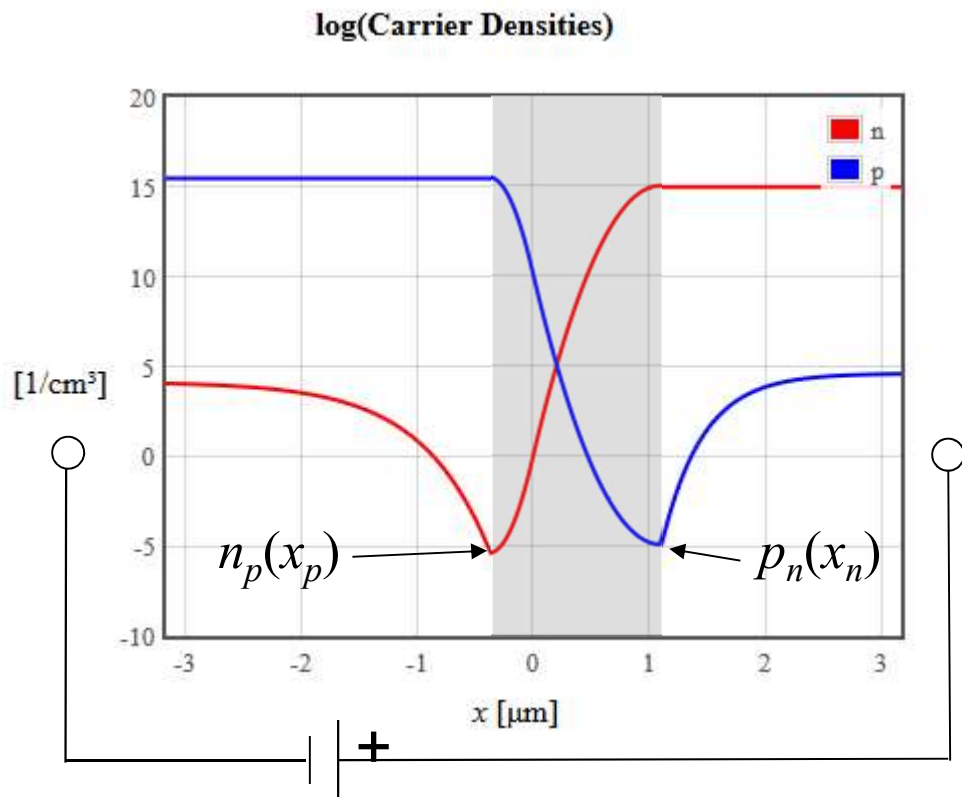
Electrons and holes are driven towards the junction.
The depletion region becomes narrower

$$n_p(x_p) = n_{p0} \exp\left(\frac{eV}{k_B T}\right)$$

$$p_n(x_n) = p_{n0} \exp\left(\frac{eV}{k_B T}\right)$$

Minority electrons are injected into the p-region
Minority holes are injected into the n-region

Reverse bias, $V < 0$



Electrons and holes are driven away from the junction.

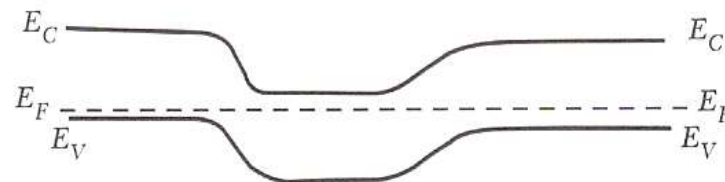
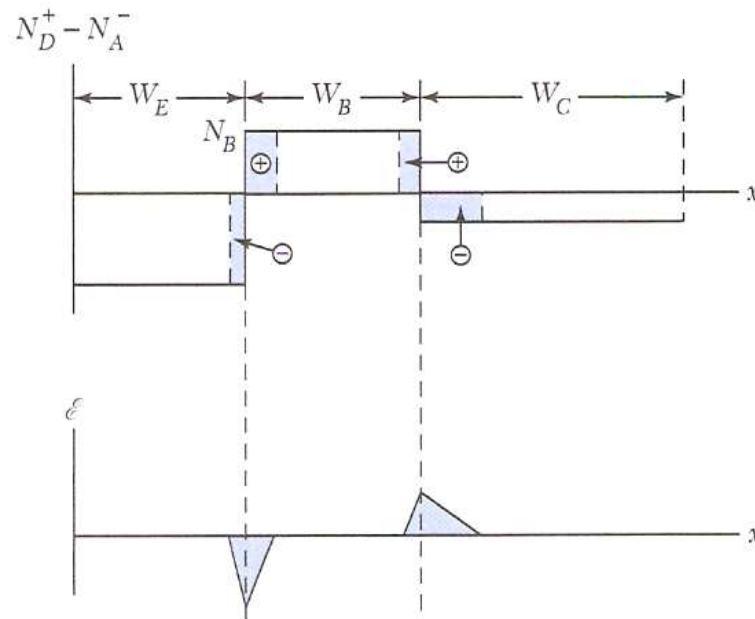
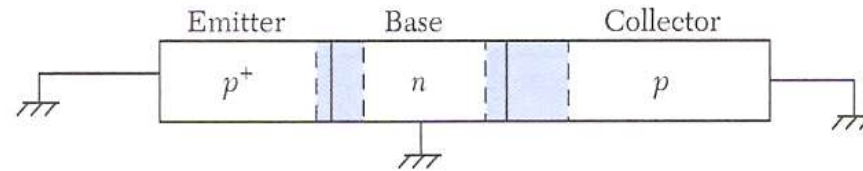
The depletion region becomes wider

$$n_p(x_p) = n_{p0} \exp\left(\frac{eV}{k_B T}\right)$$

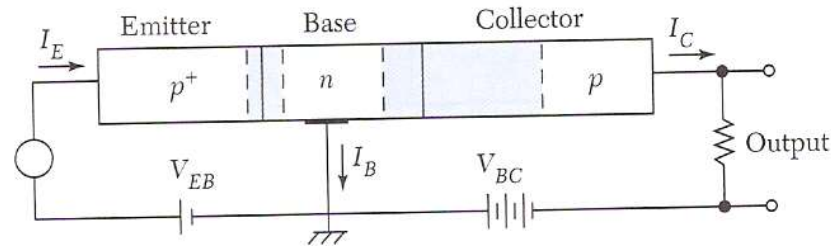
$$p_n(x_n) = p_{n0} \exp\left(\frac{eV}{k_B T}\right)$$

Minority electrons are extracted from the p-region by the electric field
Minority holes are extracted from the n-region by the electric field

pnp transistor, no bias

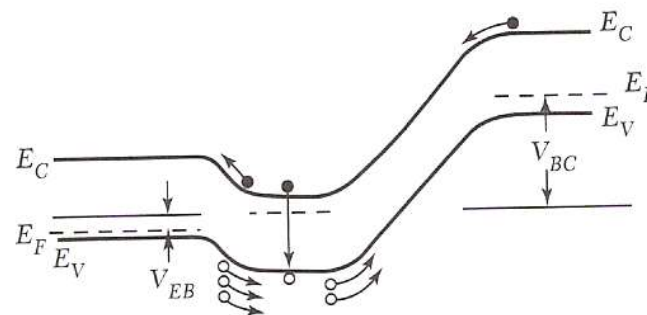
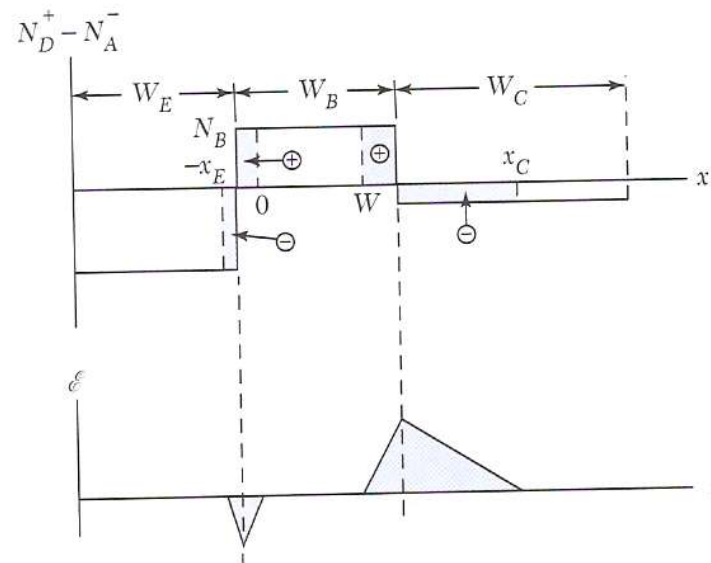


pnp transistor, forward active bias

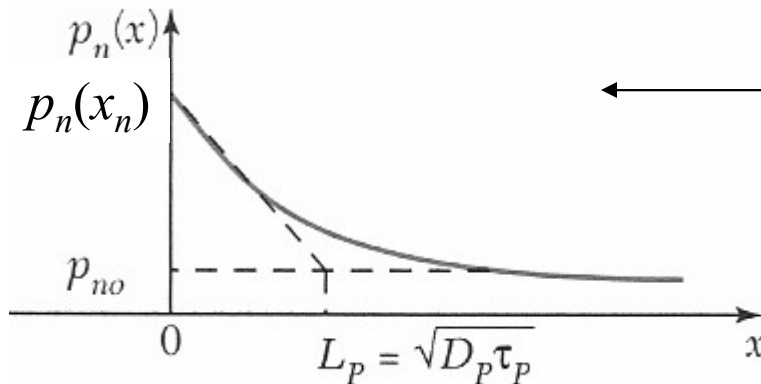


Always dissipate power due to the forward bias

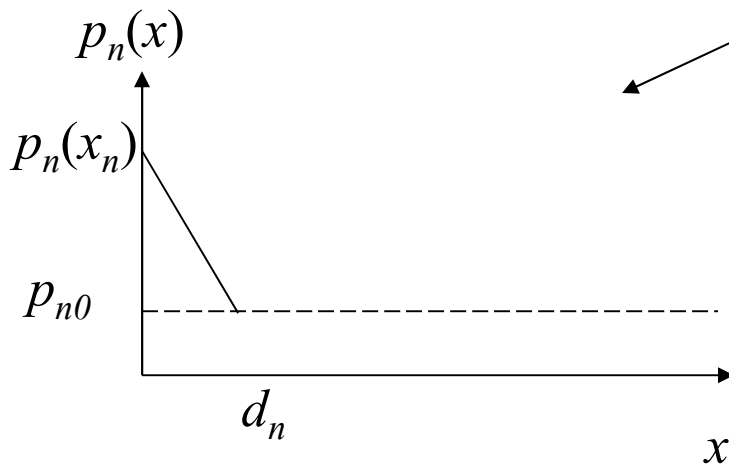
The base-emitter voltage controls the minority carriers injected from the emitter to the base. These diffuse to the base-collector junction and are swept into the collector.



Long/Short diode



← Long diode $d_n \gg L_p$



Short diode

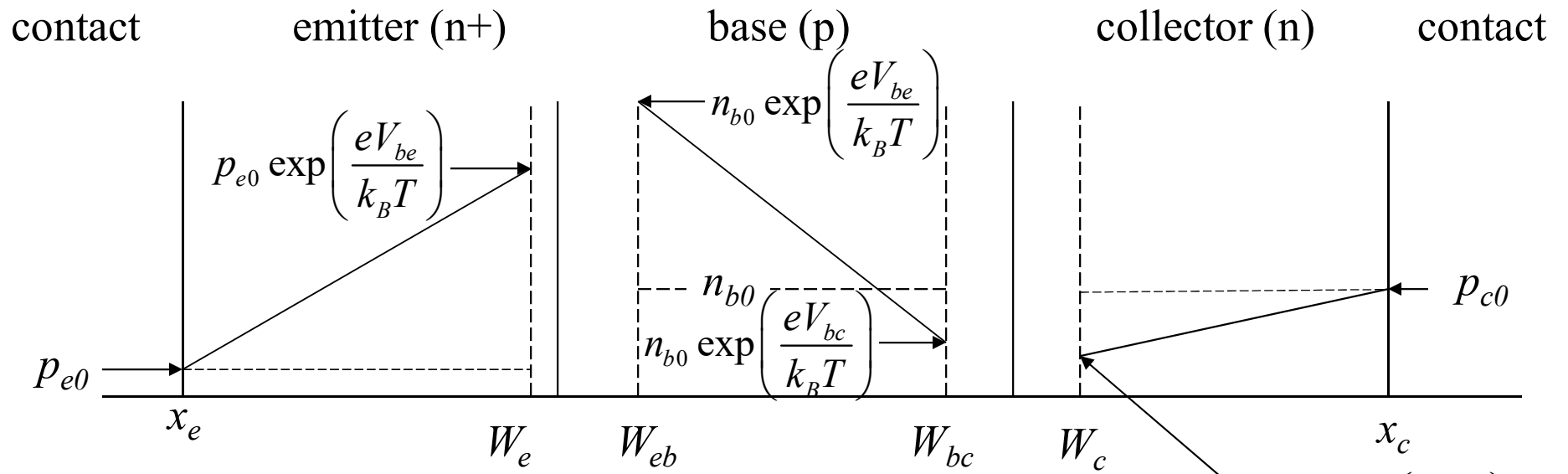
$d_n \ll L_p$

Metal contact is much closer to the depletion region than the diffusion length

$$J_{diff,p} = -eD_p \frac{dp}{dx}$$

$$J_{diff,p} = -eD_p \frac{dp}{dx} = eD_p \frac{(p_n(x_n) - p_{n0})}{d_n}$$

Minority carrier concentration



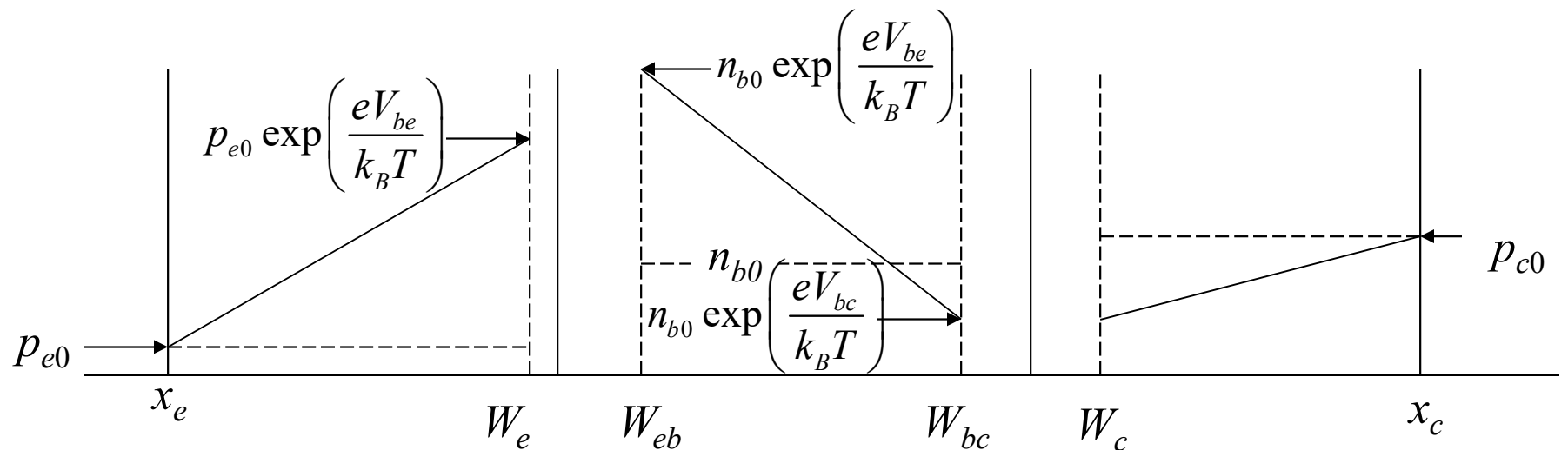
$$I_{Ep} = -eA_{be}D_p \frac{p_{e0}(e^{eV_{be}/k_B T} - 1)}{W_e - x_e}$$

$$I_{En} = eA_{be}D_n \frac{n_{b0}(e^{eV_{bc}/k_B T} - e^{eV_{be}/k_B T})}{W_{bc} - W_{be}}$$

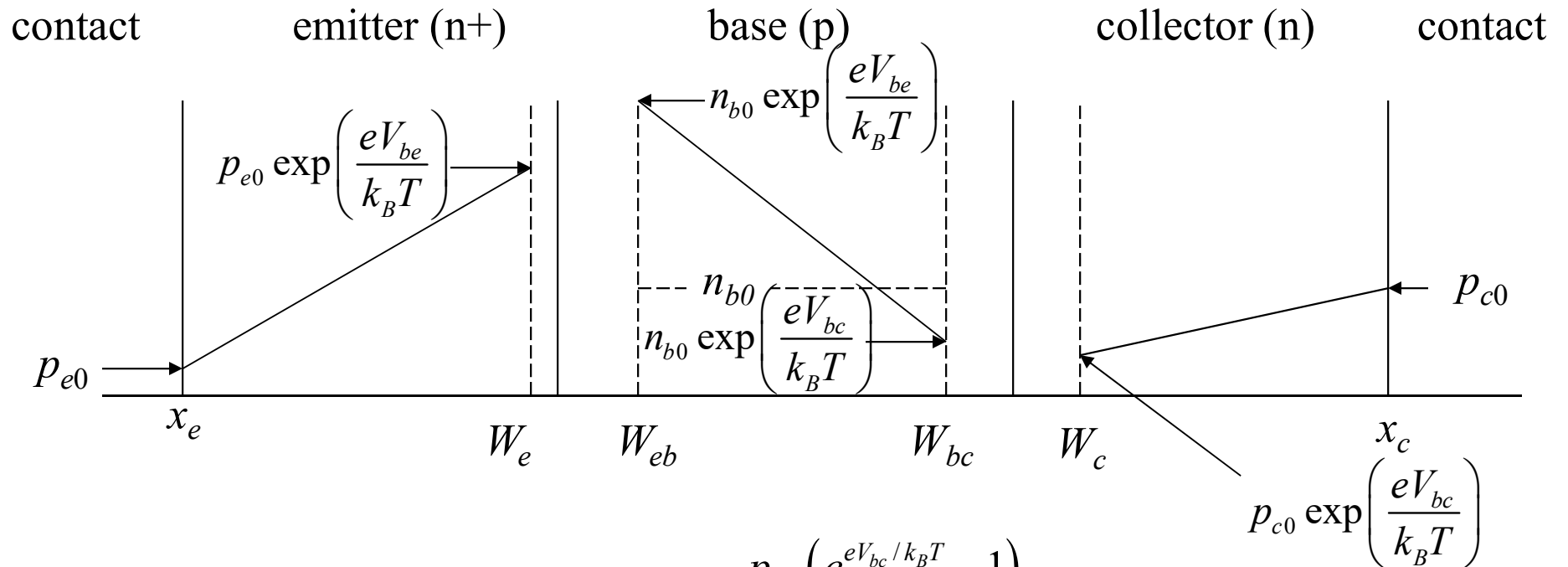
Emitter current

$$I_E = I_{En} + I_{Ep} = \left[\frac{eA_{be}D_p p_{e0}}{W_{eb} - x_e} + \frac{eA_{be}D_n n_{b0}}{W_{bc} - W_{be}} \right] \left(e^{eV_{be}/k_B T} - 1 \right) - \frac{eA_{be}D_n n_{b0}}{W_{bc} - W_{be}} \left(e^{eV_{bc}/k_B T} - 1 \right)$$

$$I_E = I_{ES} \left(e^{eV_{be}/k_B T} - 1 \right) - \alpha_R I_{CS} \left(e^{eV_{bc}/k_B T} - 1 \right)$$



Collector current



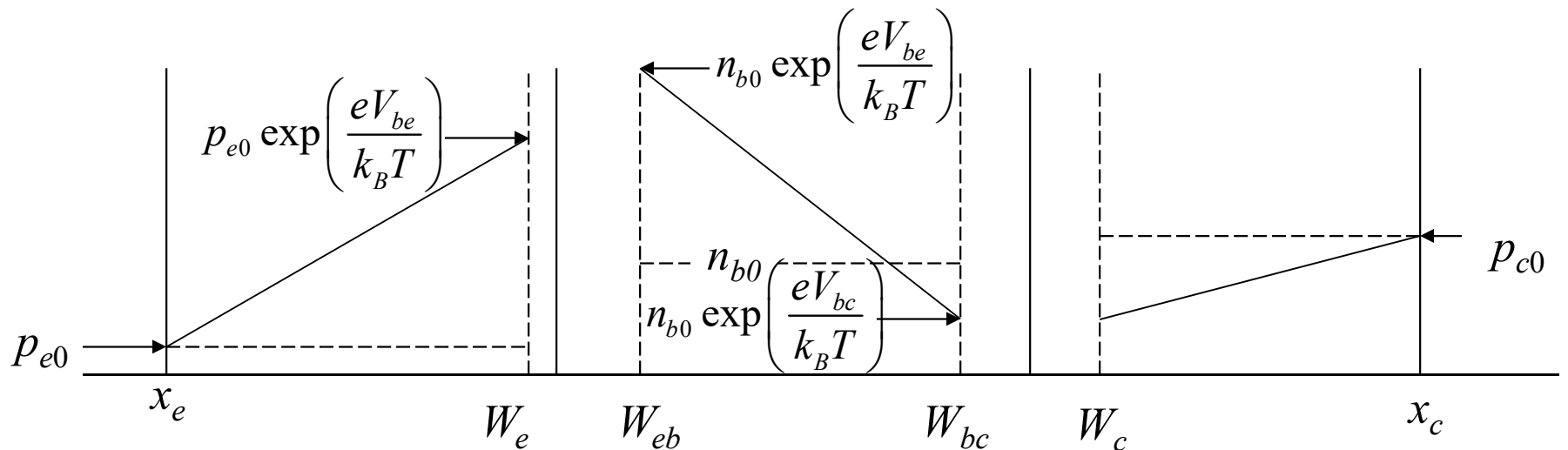
$$I_{cp} = -eA_{bc}D_p \frac{p_{c0} \left(e^{eV_{bc}/k_B T} - 1 \right)}{x_c - W_c}$$

$$I_{cn} = -eA_{bc}D_n \frac{n_{b0} \left(e^{eV_{be}/k_B T} - e^{eV_{bc}/k_B T} \right)}{W_{bc} - W_{eb}}$$

Collector current

$$I_c = I_{cp} + I_{cn} = \frac{eA_{bc}D_n n_{b0}}{W_{bc} - W_{be}} \left(e^{eV_{be}/k_B T} - 1 \right) - \left[\frac{eA_{bc}D_p p_{c0}}{x_c - W_c} + \frac{eA_{bc}D_n n_{b0}}{W_{bc} - W_{be}} \right] \left(e^{eV_{bc}/k_B T} - 1 \right)$$

$$I_c = I_{cp} + I_{cn} = \alpha_F I_{ES} \left(e^{eV_{be}/k_B T} - 1 \right) - I_{CS} \left(e^{eV_{bc}/k_B T} - 1 \right)$$

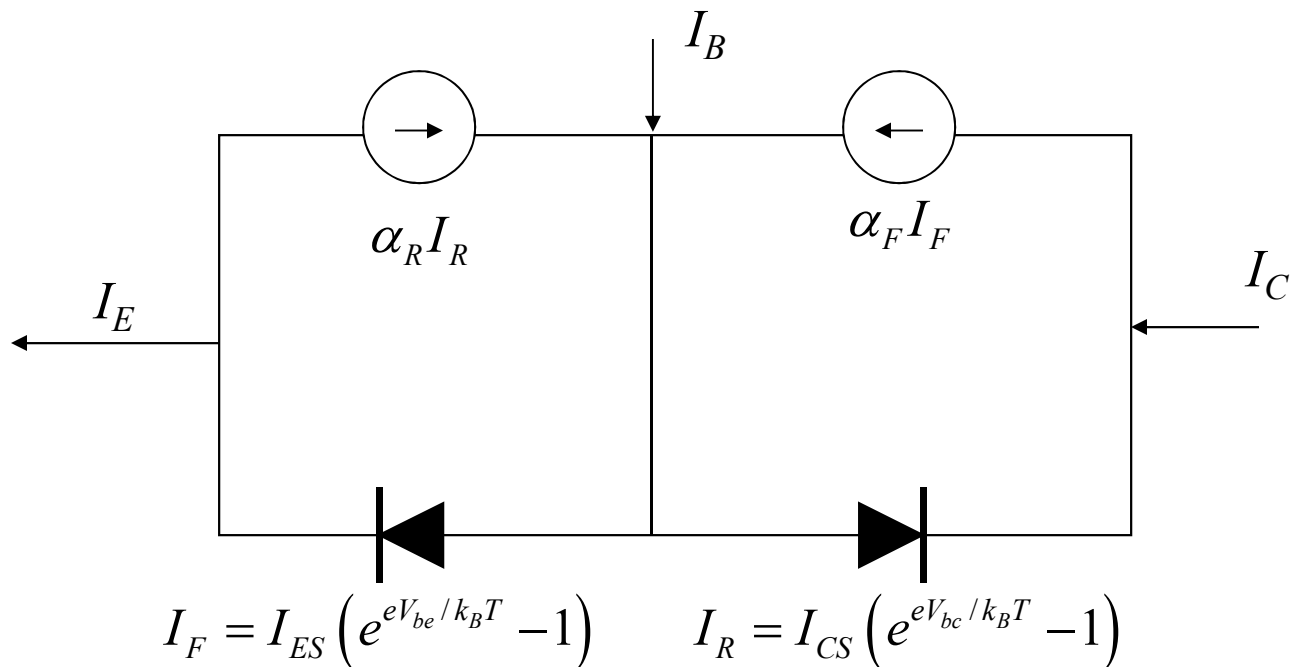


Ebers-Moll model

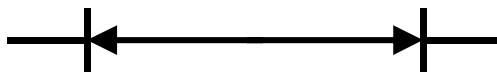
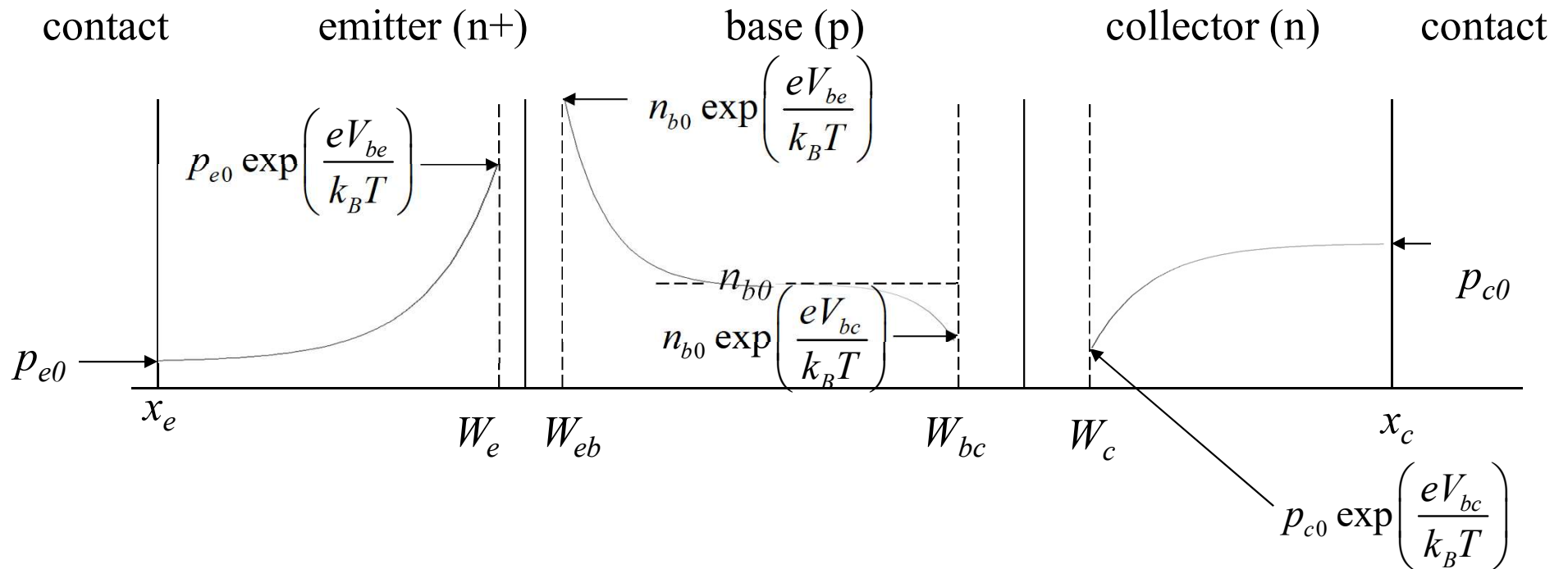
$$I_E = I_{ES} \left(e^{eV_{be}/k_B T} - 1 \right) - \alpha_R I_{CS} \left(e^{eV_{bc}/k_B T} - 1 \right)$$

$$I_C = \alpha_F I_{ES} \left(e^{eV_{be}/k_B T} - 1 \right) - I_{CS} \left(e^{eV_{bc}/k_B T} - 1 \right)$$

$$I_B = I_E - I_C$$

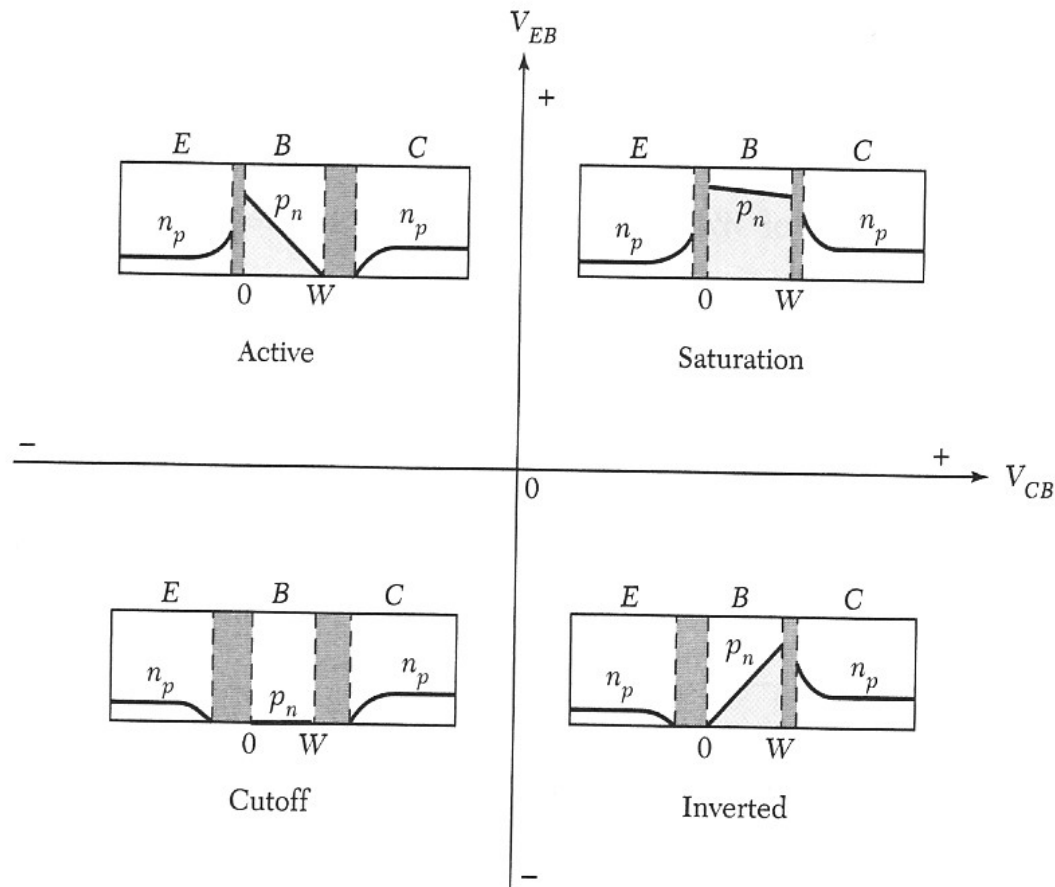


Not an npn transistor



Transistor modes

1. Forward active: emitter-base **forward**, base-collector **reverse**
2. Saturation: emitter-base **forward**, base-collector **forward**
3. Reverse active: emitter-base **reverse**, base-collector **forward**
4. Cut-off: emitter-base **reverse**, base-collector **reverse**



Emitter efficiency

$$\gamma_e = \frac{I_{En}}{I_{En} + I_{Ep}} = \frac{1}{1 + I_{Ep} / I_{En}} \quad \leftarrow \text{for npn}$$

$$I_{Ep} = eA_{be}D_p \frac{p_{e0} \left(e^{eV_{be}/k_B T} - 1 \right)}{W_{eb} - x_e}$$

$$I_{En} = -eA_{be}D_n \frac{n_{b0} \left(e^{eV_{be}/k_B T} - e^{eV_{bc}/k_B T} \right)}{W_{bc} - W_{be}}$$

For $\gamma_e \sim 1$, $W_{bc} - W_{be} \ll L_b$, $W_{eb} - x_e$ and $n_{b0} \gg p_{e0}$

neutral base width

$$\frac{n_i^2}{N_{Ab}}$$

$$\frac{n_i^2}{N_{De}}$$

Small base width and heavy emitter doping

Base transport factor

$$B = \frac{I_c}{I_{En}}$$

ratio of the injected current to the collected current

recombination in the base would reduce the base transport factor

A thin base with low doping results in a base transport factor ~ 1

Current transfer ratio

$$\alpha = \frac{I_C}{I_E} = B\gamma_e$$

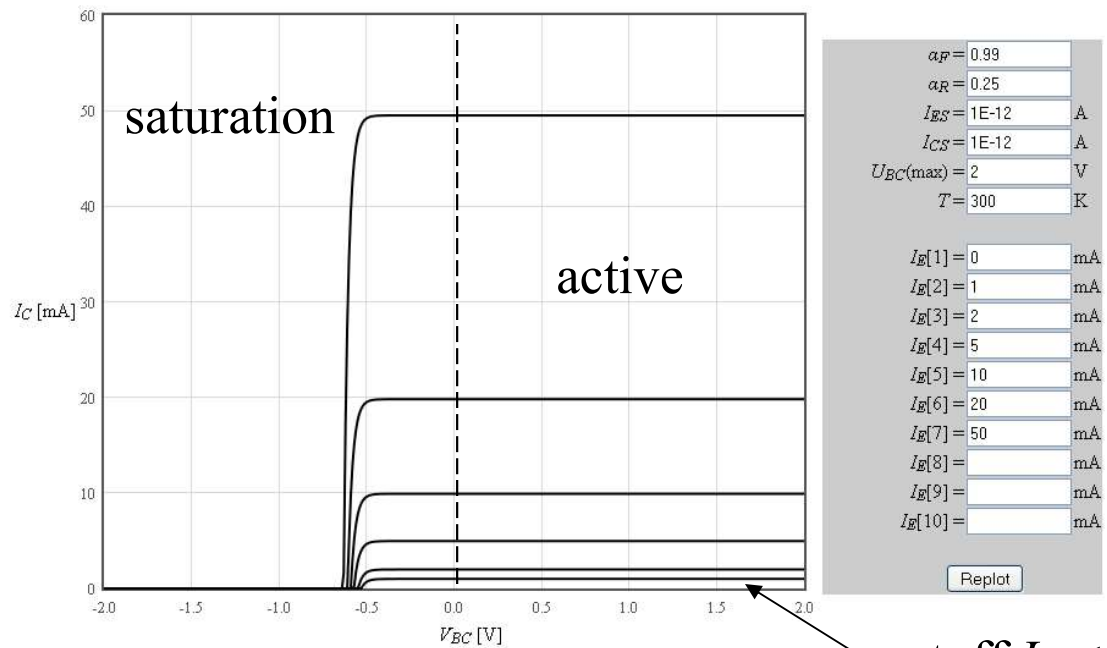
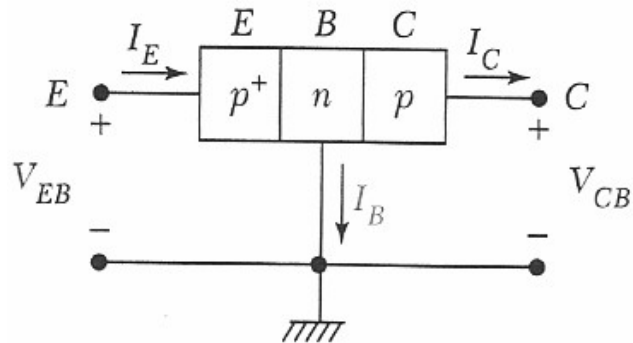
$\alpha \sim 1$ for a good BJT

Common base configuration

$$I_E = I_{ES} \left(e^{eV_{be}/k_B T} - 1 \right) - \alpha_R I_{CS} \left(e^{eV_{bc}/k_B T} - 1 \right)$$

solve for V_{be}

$$I_C = \alpha_F I_{ES} \left(e^{eV_{be}/k_B T} - 1 \right) - I_{CS} \left(e^{eV_{bc}/k_B T} - 1 \right)$$

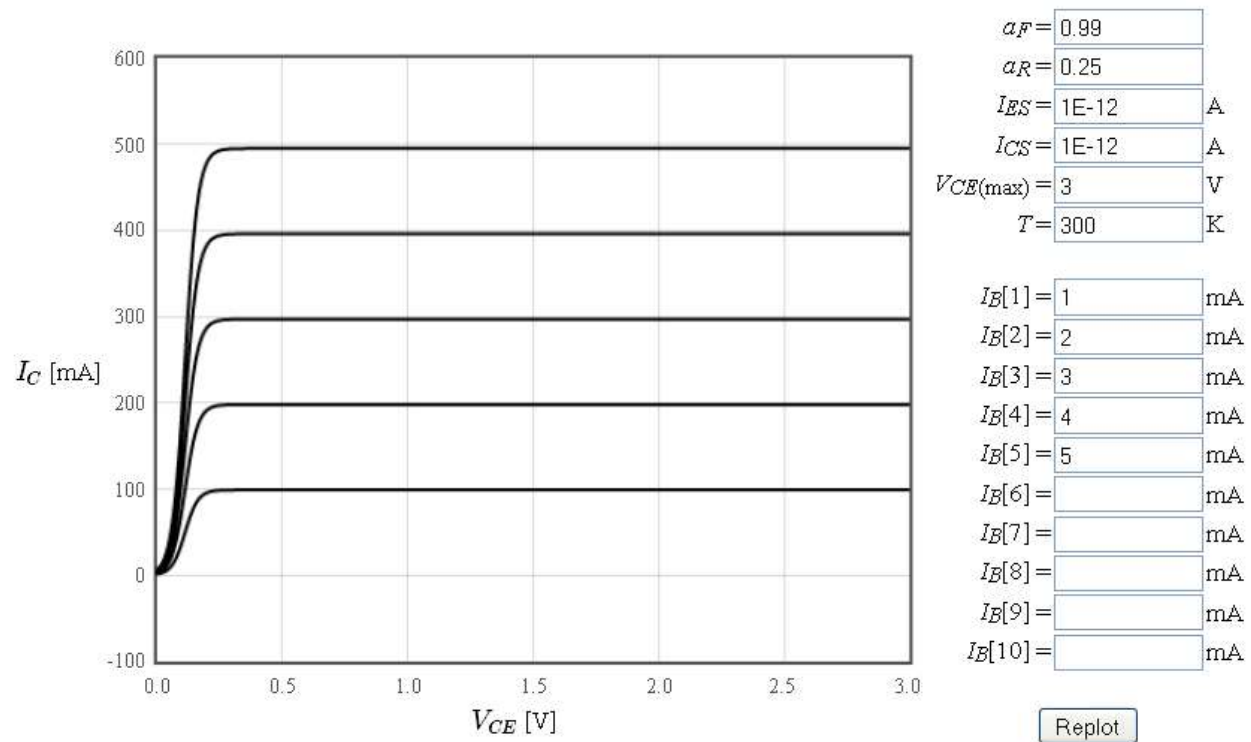
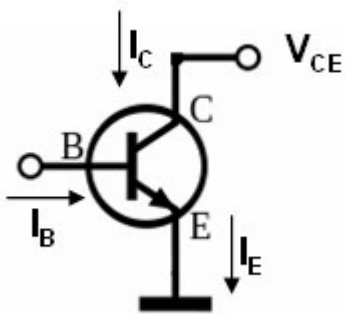


cutoff $I_E < 0$

Common emitter configuration

$$I_E = I_{ES} \left(e^{eV_{be}/k_B T} - 1 \right) - \alpha_R I_{CS} \left(e^{eV_{bc}/k_B T} - 1 \right) \quad I_B = I_E - I_C$$

$$I_C = \alpha_F I_{ES} \left(e^{eV_{be}/k_B T} - 1 \right) - I_{CS} \left(e^{eV_{bc}/k_B T} - 1 \right)$$



current amplification ~ 100

Current amplification factor

$$\beta = h_{fe} = \frac{I_C}{I_B}$$

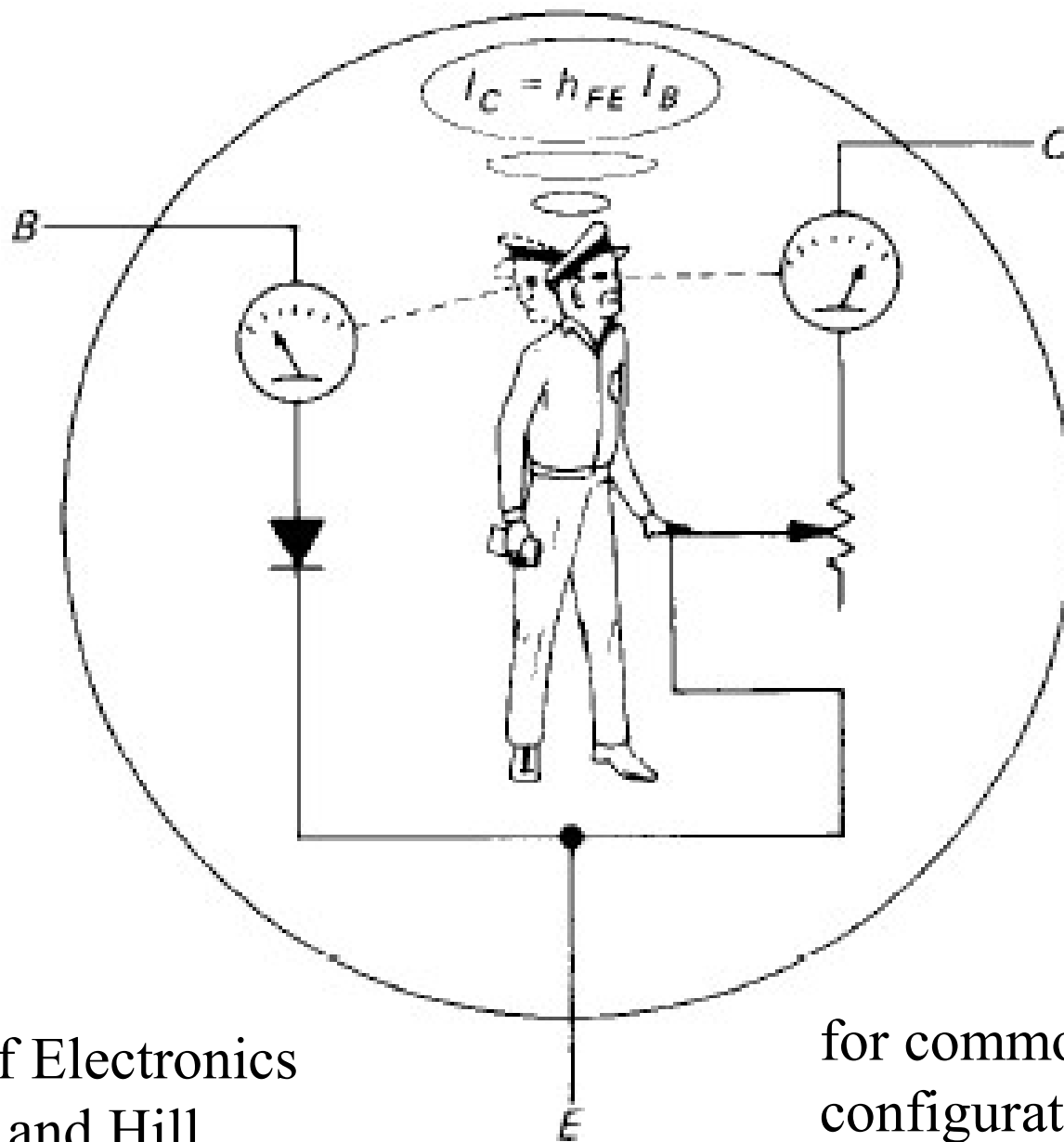
$$I_B = I_E - I_C$$

$$I_C = \alpha I_E$$

$$I_B = \left(\frac{1}{\alpha} - 1 \right) I_C$$

$$\beta = \frac{I_C}{I_B} = \frac{\alpha}{1 - \alpha} = \frac{B\gamma_e}{1 - B\gamma_e}$$

$$\beta \sim 50 - 500$$



The Art of Electronics
Horowitz and Hill

for common emitter
configuration

“Transistor man”

Transconductance

$$g_m = \frac{\partial I_C}{\partial V_{be}}$$

$$I_c = \alpha_F I_{ES} \left(e^{eV_{be}/k_B T} - 1 \right) - I_{CS} \left(e^{eV_{bc}/k_B T} - 1 \right)$$

The first term depends on V_{be}

$$g_m = \frac{e\alpha_F I_{ES}}{k_B T} e^{eV_{be}/k_B T} \approx \frac{eI_C}{k_B T} = \frac{e\beta I_B}{k_B T}$$

The transconductance can be very high.

Early effect

Ebers - Moll:

$$I_E = I_{ES} \left(e^{eV_{be}/k_B T} - 1 \right) - \alpha_R I_{CS} \left(e^{eV_{bc}/k_B T} - 1 \right)$$

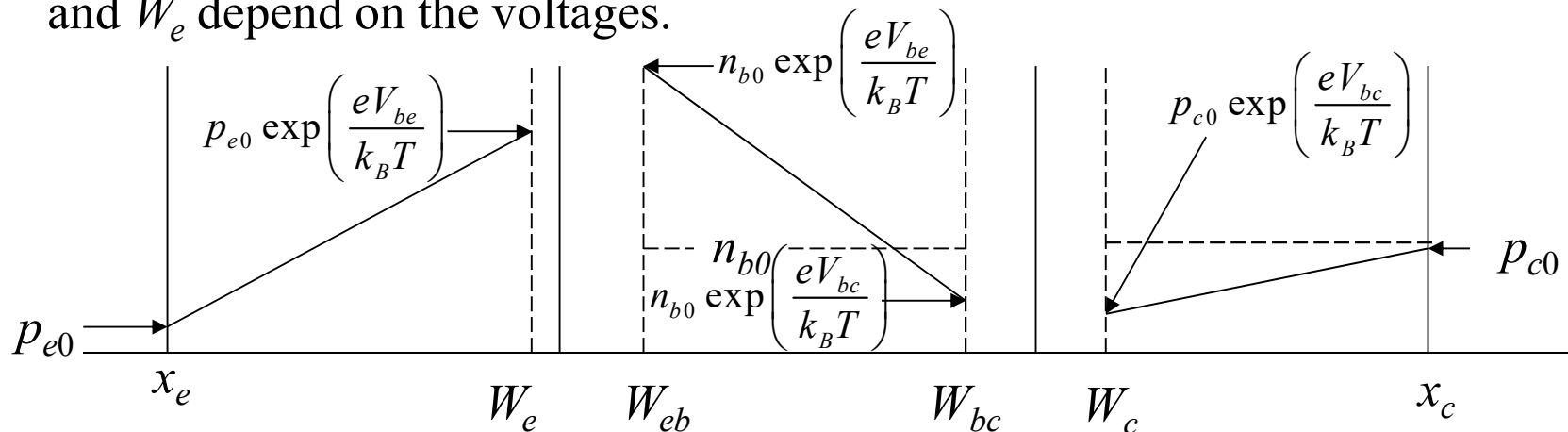
$$I_C = \alpha_F I_{ES} \left(e^{eV_{be}/k_B T} - 1 \right) - I_{CS} \left(e^{eV_{bc}/k_B T} - 1 \right)$$

$$I_B = I_E - I_C$$

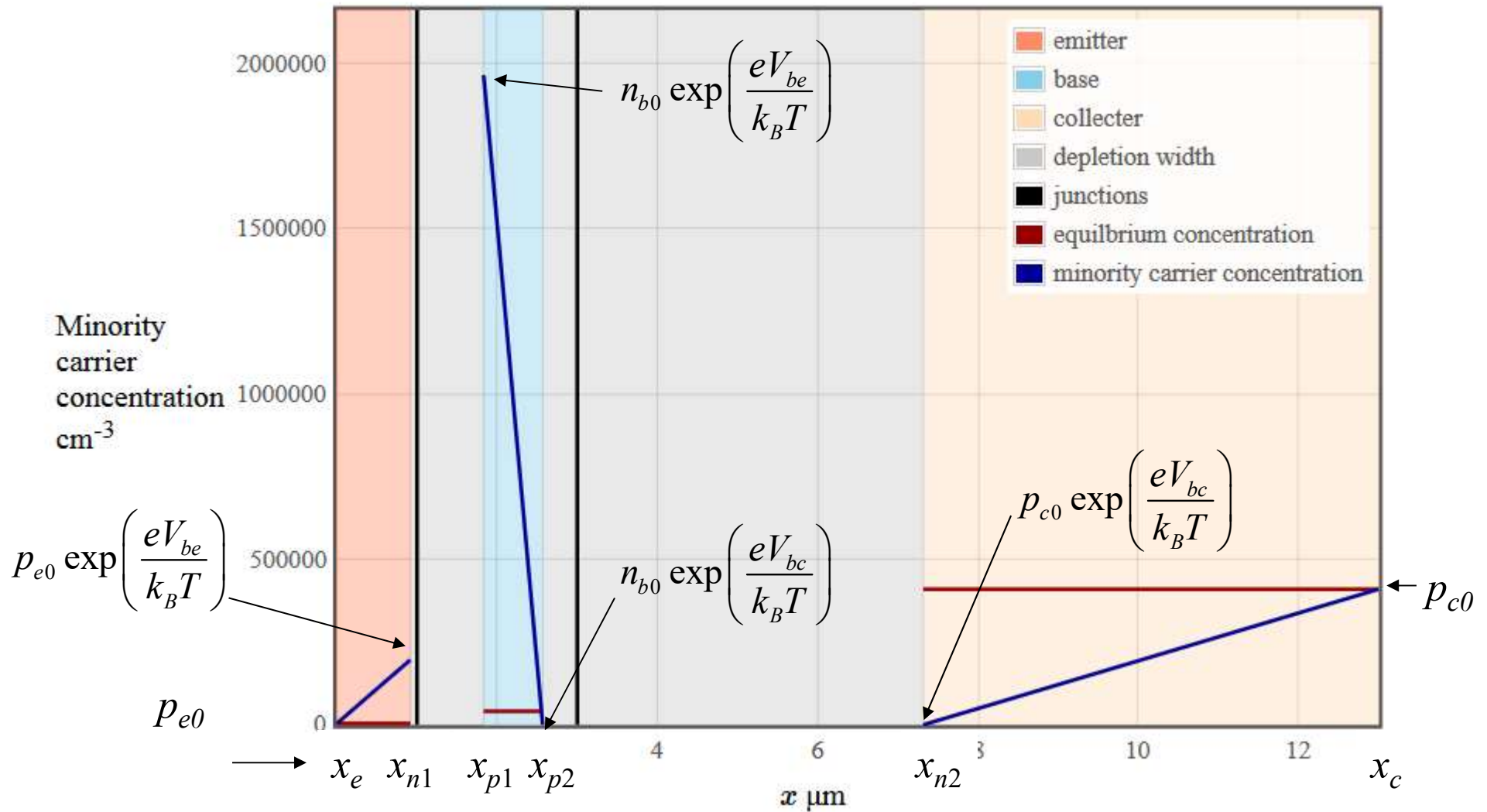
$$I_{ES} = \left[\frac{eA_{be}D_p p_{e0}}{W_{eb} - x_e} + \frac{eA_{be}D_n n_{b0}}{W_{bc} - W_{be}} \right]$$

$$I_{CS} = \left[\frac{eA_{bc}D_p p_{c0}}{x_c - W_c} + \frac{eA_{bc}D_n n_{b0}}{W_{bc} - W_{be}} \right]$$

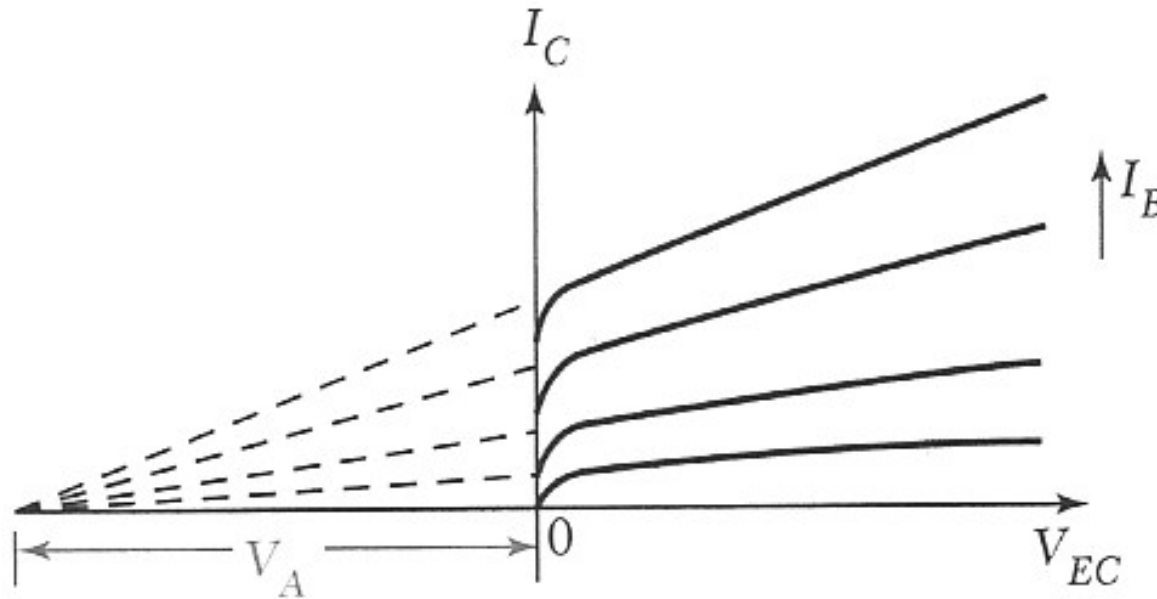
I_{ES} and I_{CS} are treated as constants but the depletion widths W_{bc} , W_{be} , W_c and W_e depend on the voltages.



Minority carrier concentration



Early effect



Common emitter configuration

Base width modulation: smaller width increases the diffusion current and increases the gain.

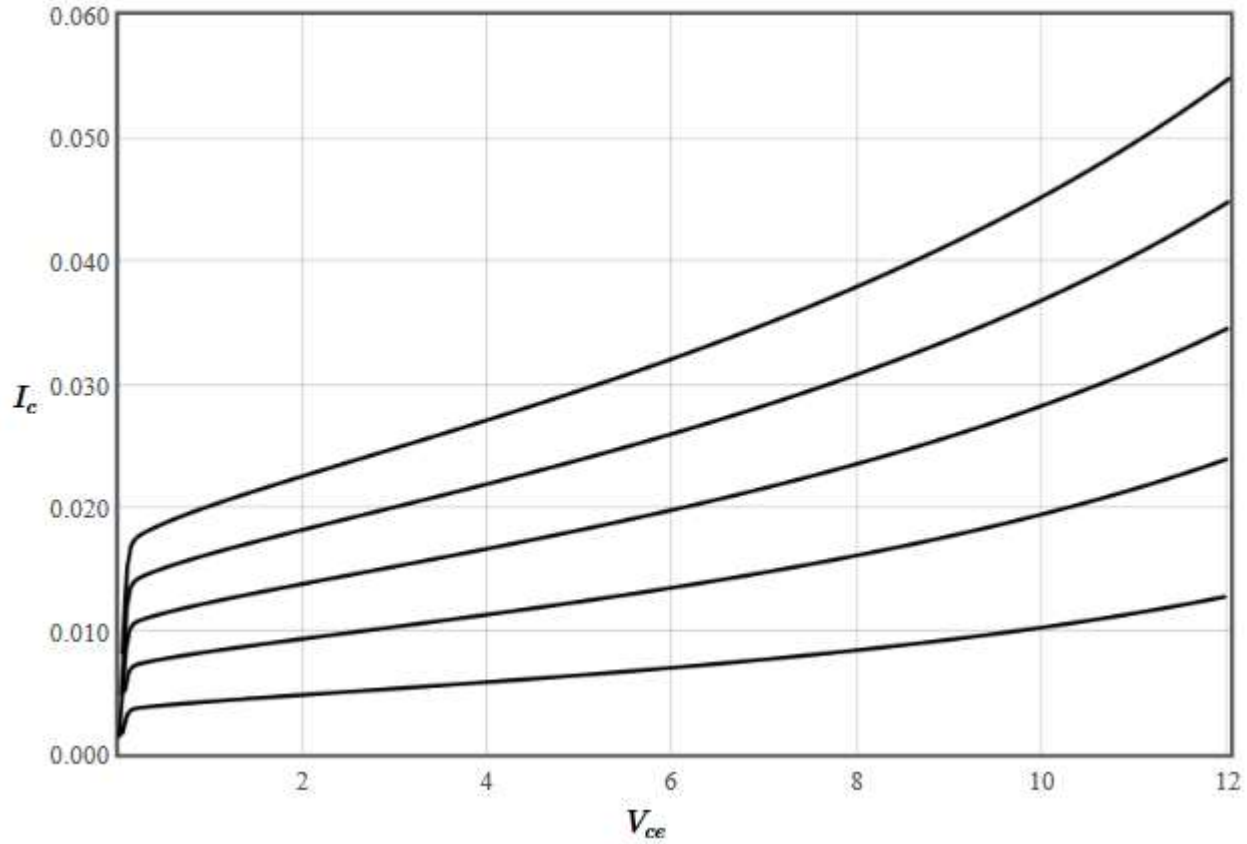
Punchthrough: The neutral base width goes to zero and all gain is lost.

Lightly dope the collector -> voltage drops in collector. Makes circuit slower.

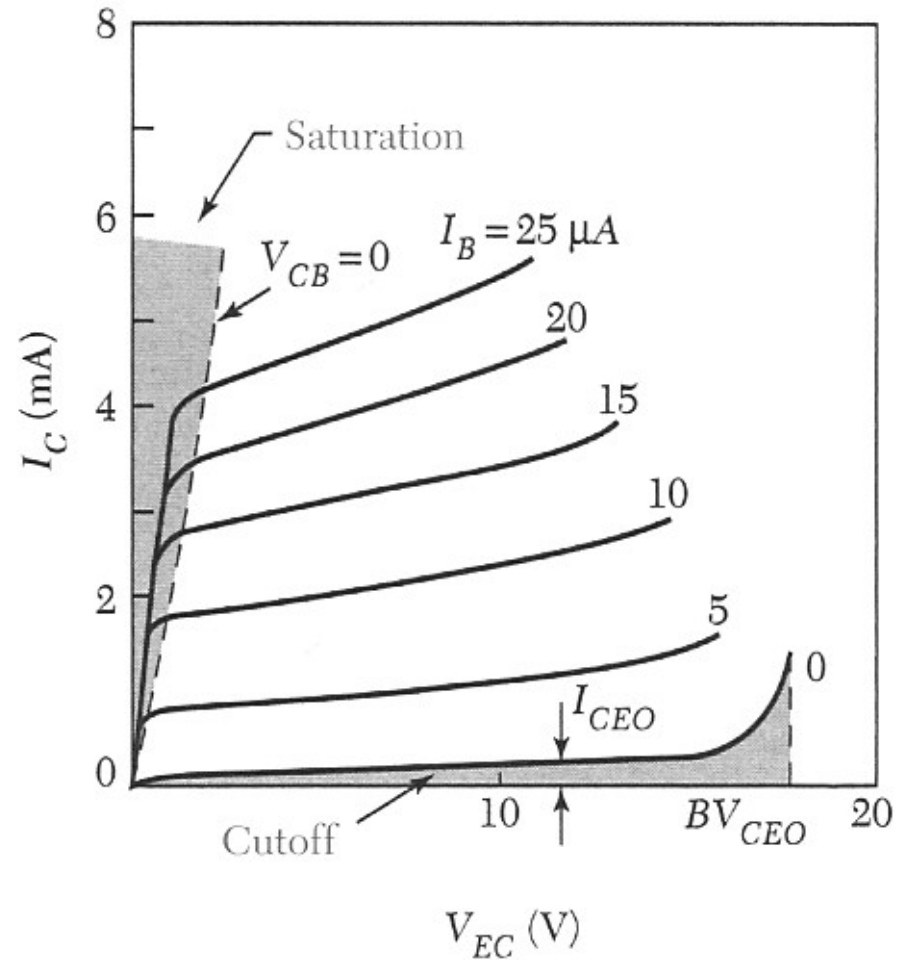
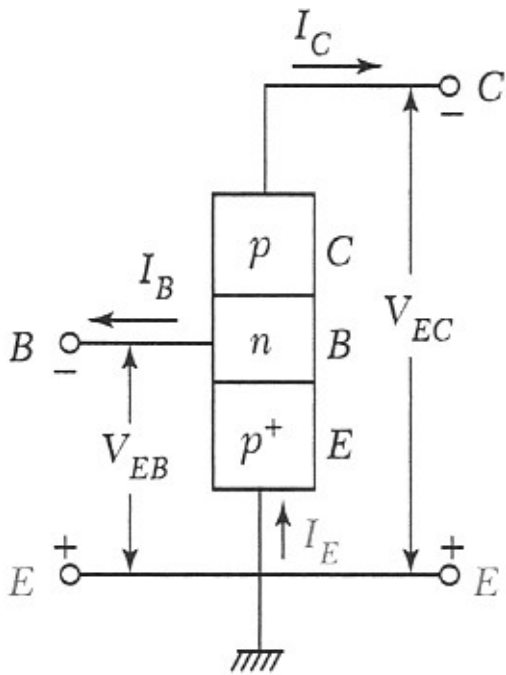
NPN common emitter configuration

n-Emitter		$A_{cb} = 1E-3$ cm ²	
Minority $\mu_{pe} = 480$ cm ² /Vs	$N_{de} = 1E16$ cm ⁻³	$N_c(300K) = 2.78E19$ cm ⁻³	$N_v(300K) = 9.84E18$ cm ⁻³
$\tau_{pe} = 1E-5$ s		$E_g = 1.166-4.73E-4*T*(T+636)$ eV	$\epsilon_r = 11.9$
p-Base		$I_{bmax} = 0.001$ eV	$V_{ce max} = 12$ eV
Minority $\mu_{nb} = 1350$ cm ² /Vs	$N_{db} = 1E15$ cm ⁻³	$x_1 - x_e = 1$ μm	$x_2 - x_1 = 2$ μm
$\tau_{nb} = 1E-5$ s		$x_c - x_2 = 10$ μm	$T = 300$ K
n-Collector			
Minority $\mu_{pc} = 480$ cm ² /Vs	$N_{dc} = 1E14$ cm ⁻³		
$\tau_{pc} = 1E-5$ s			
<input type="button" value="Calculate"/>			

$$I_C \sim \beta I_B$$

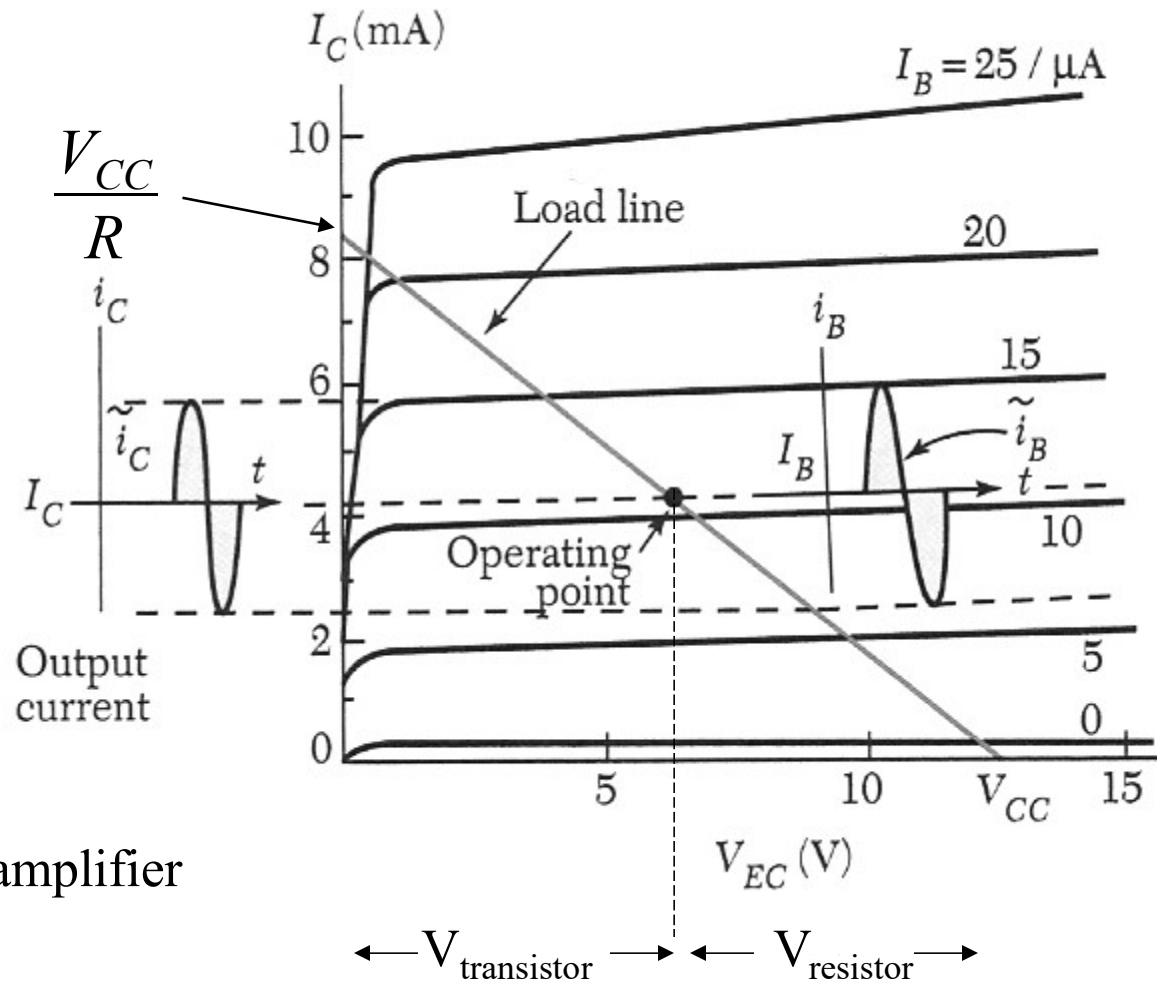
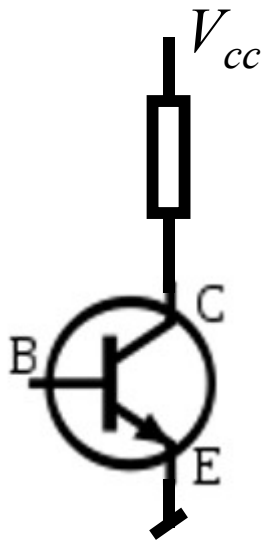


Common emitter configuration



$$I_C \sim \beta I_B \text{ amplifier}$$

Small signal response



Low input impedance amplifier

Small signal response

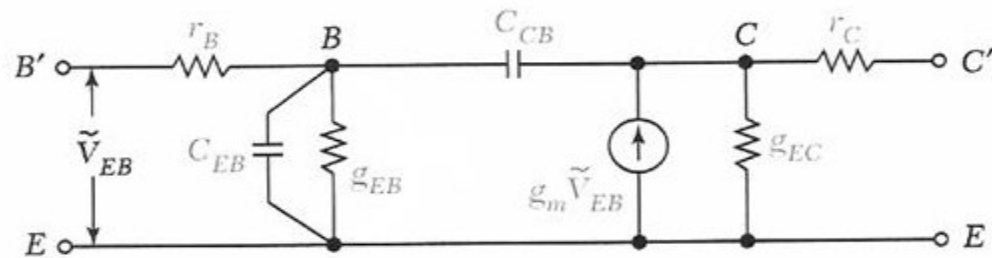
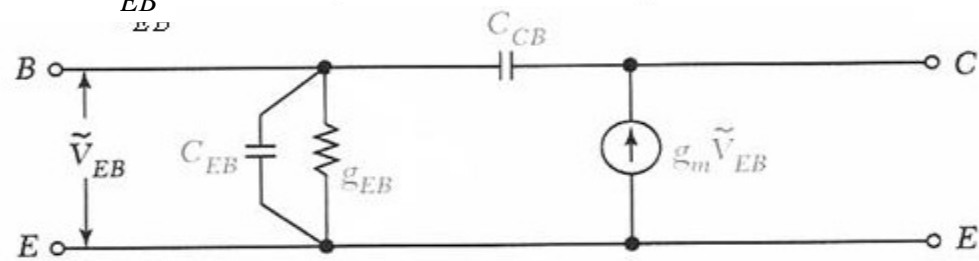
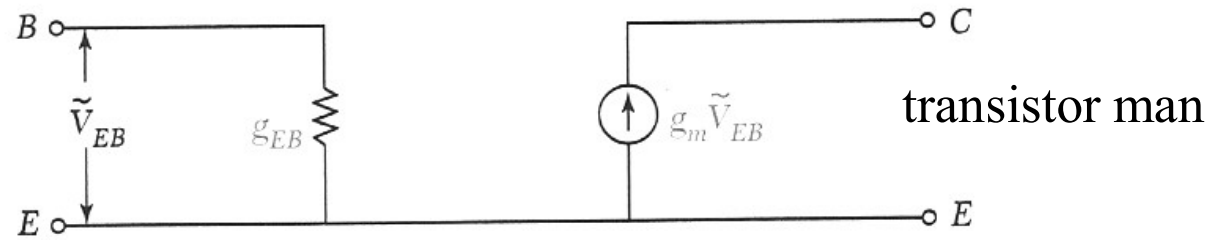
$$\tilde{i}_c = \beta \tilde{i}_B = \beta g_{EB} \tilde{v}_{EB}$$

input conductance:

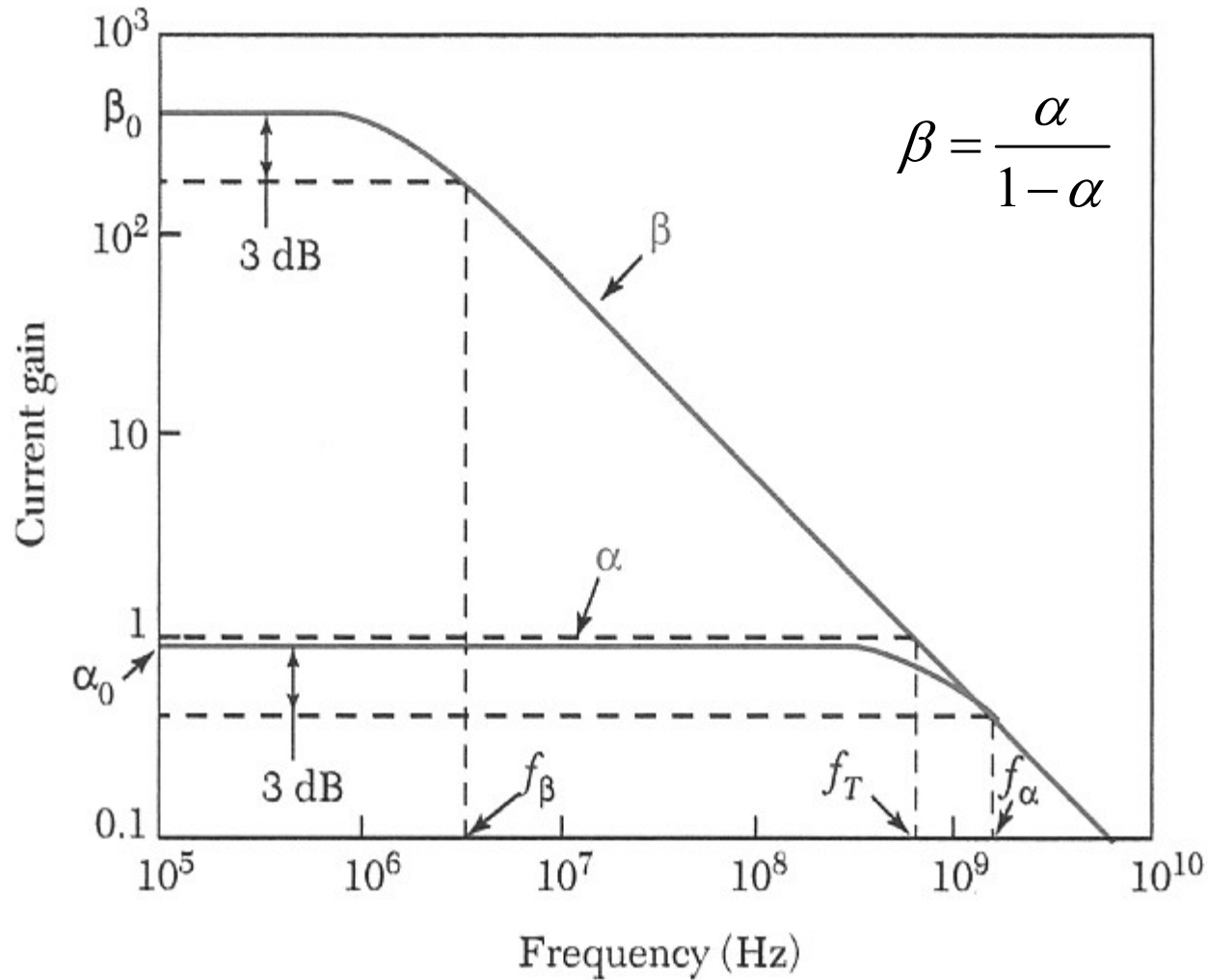
$$g_{EB} = \frac{\tilde{i}_B}{\tilde{v}_{EB}}$$

transconductance:

$$g_m = \frac{\tilde{i}_c}{\tilde{v}_{EB}}$$



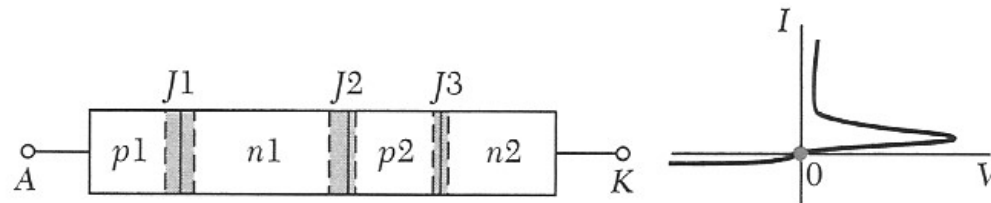
Small signal response



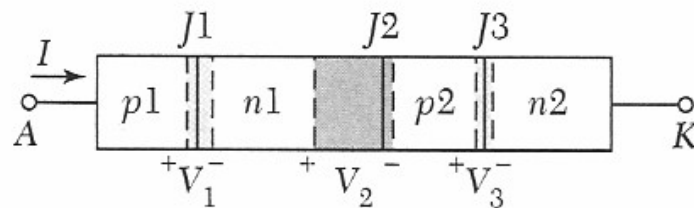
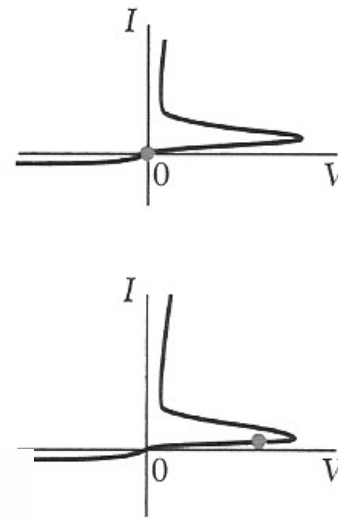
$$f_\beta = (1 - \alpha_0) f_\alpha$$

$$f_T = \alpha_0 f_\alpha$$

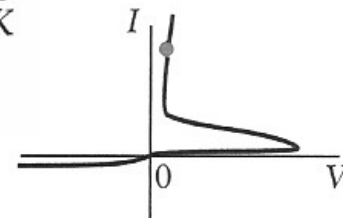
Thyristors



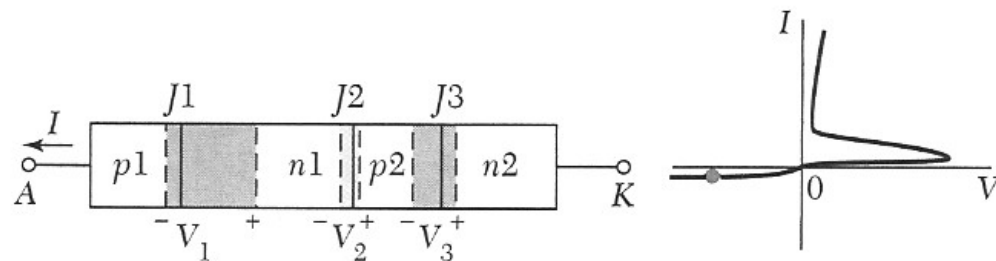
Forward blocking



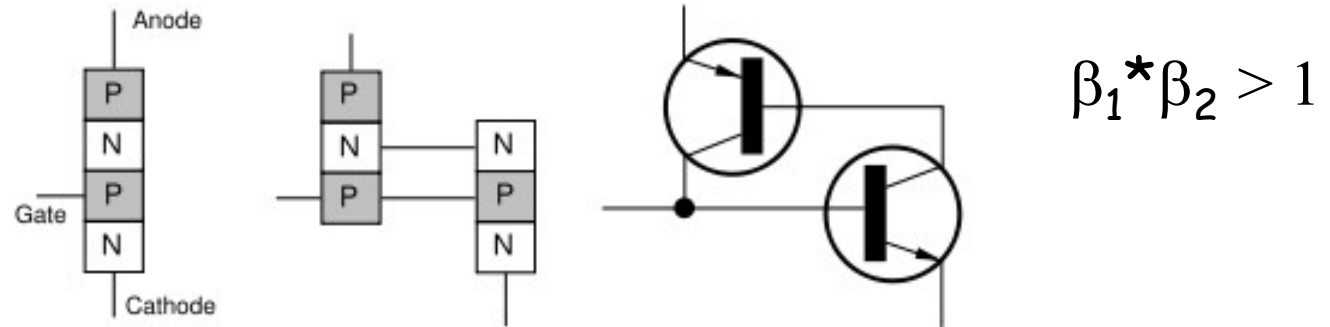
Forward conducting



Reverse blocking



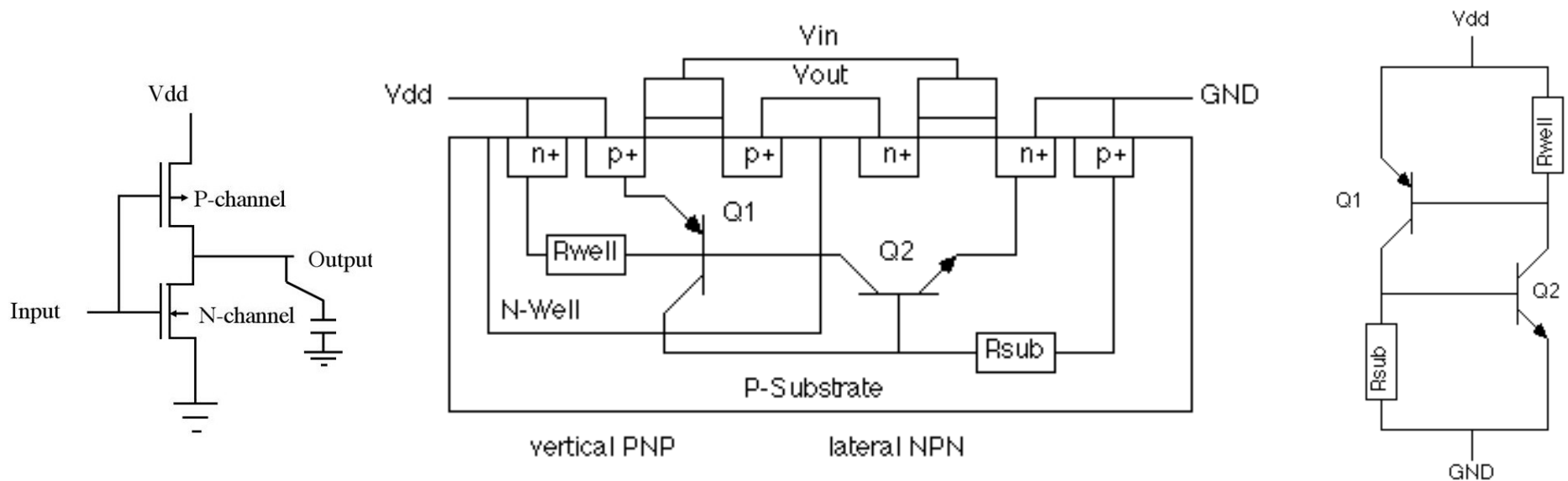
Thyristors



Used for switching high currents or voltages



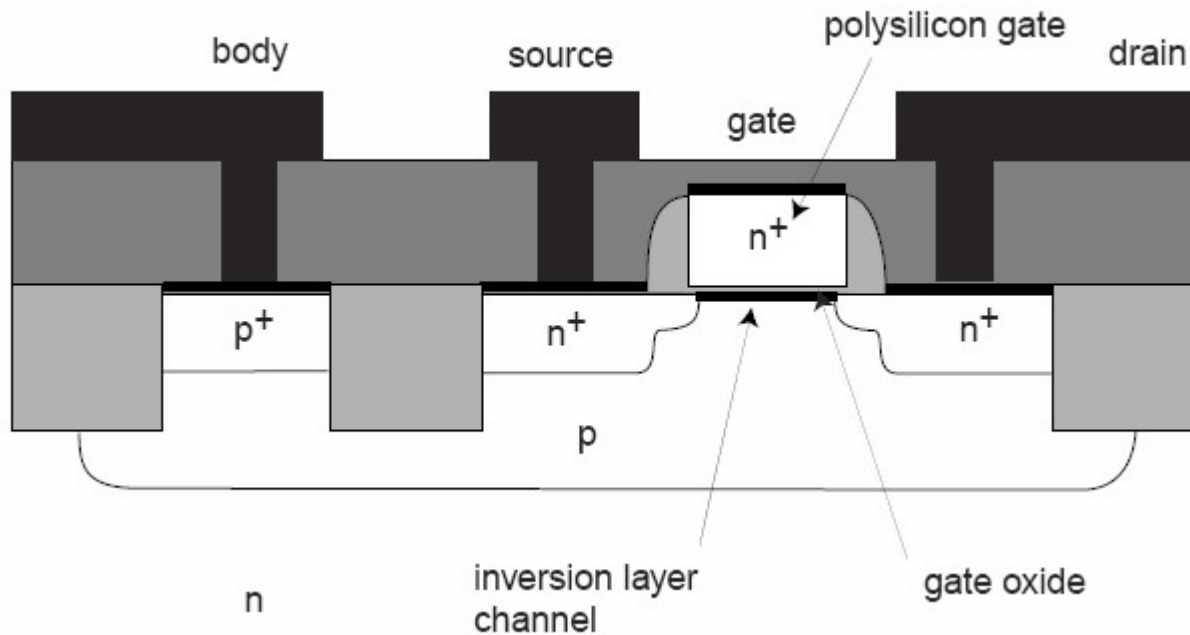
Latch-up



Both BJT's conduct, creating a low resistance path between V_{dd} and GND. The product of the gains of the two transistors in the feedback loop, is greater than one. The result of latchup is at the minimum a circuit malfunction, and in the worst case, the destruction of the device.

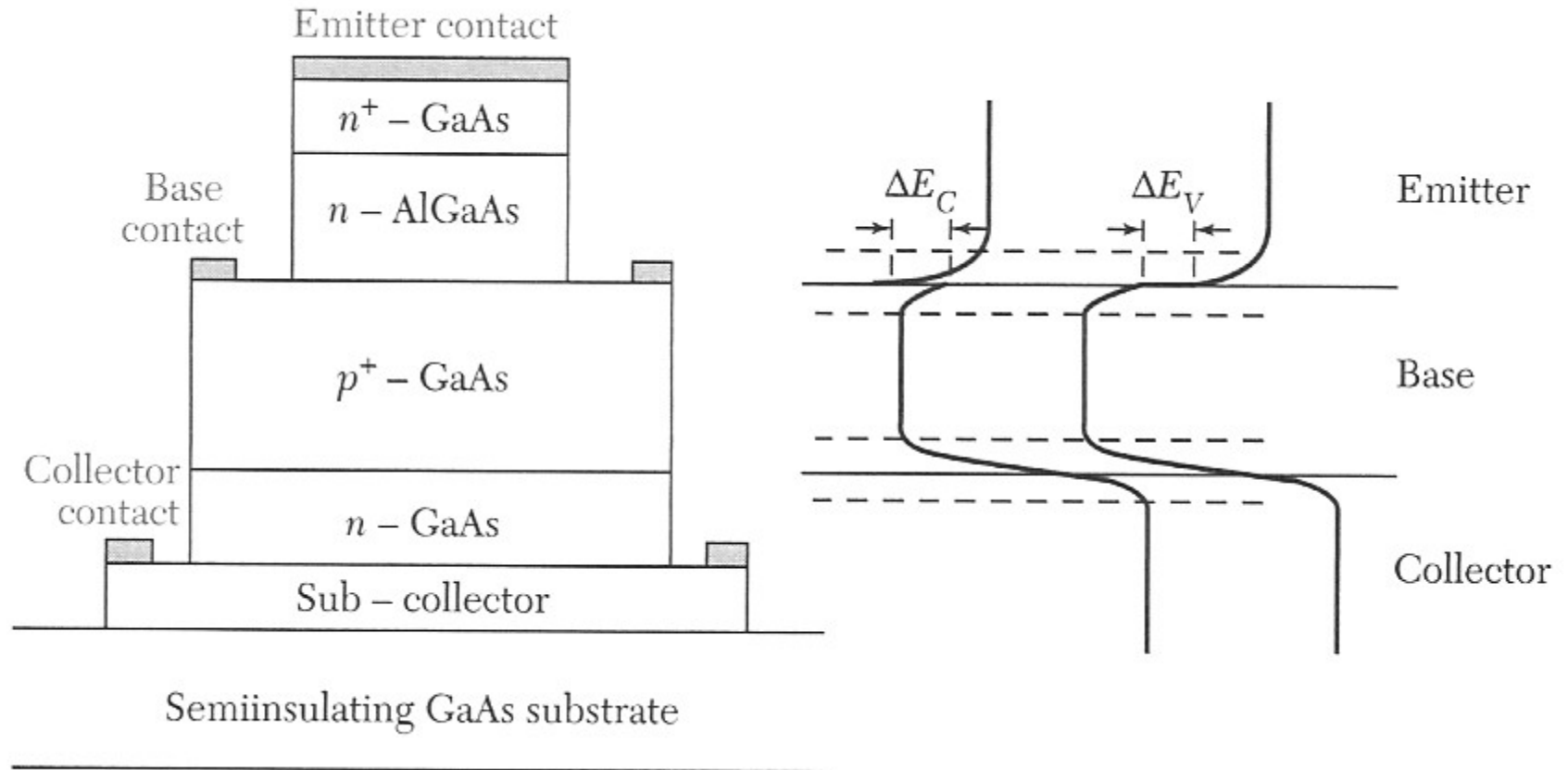
<http://www.ece.drexel.edu/courses/ECE-E431/latch-up/latch-up.html>

Subthreshold current

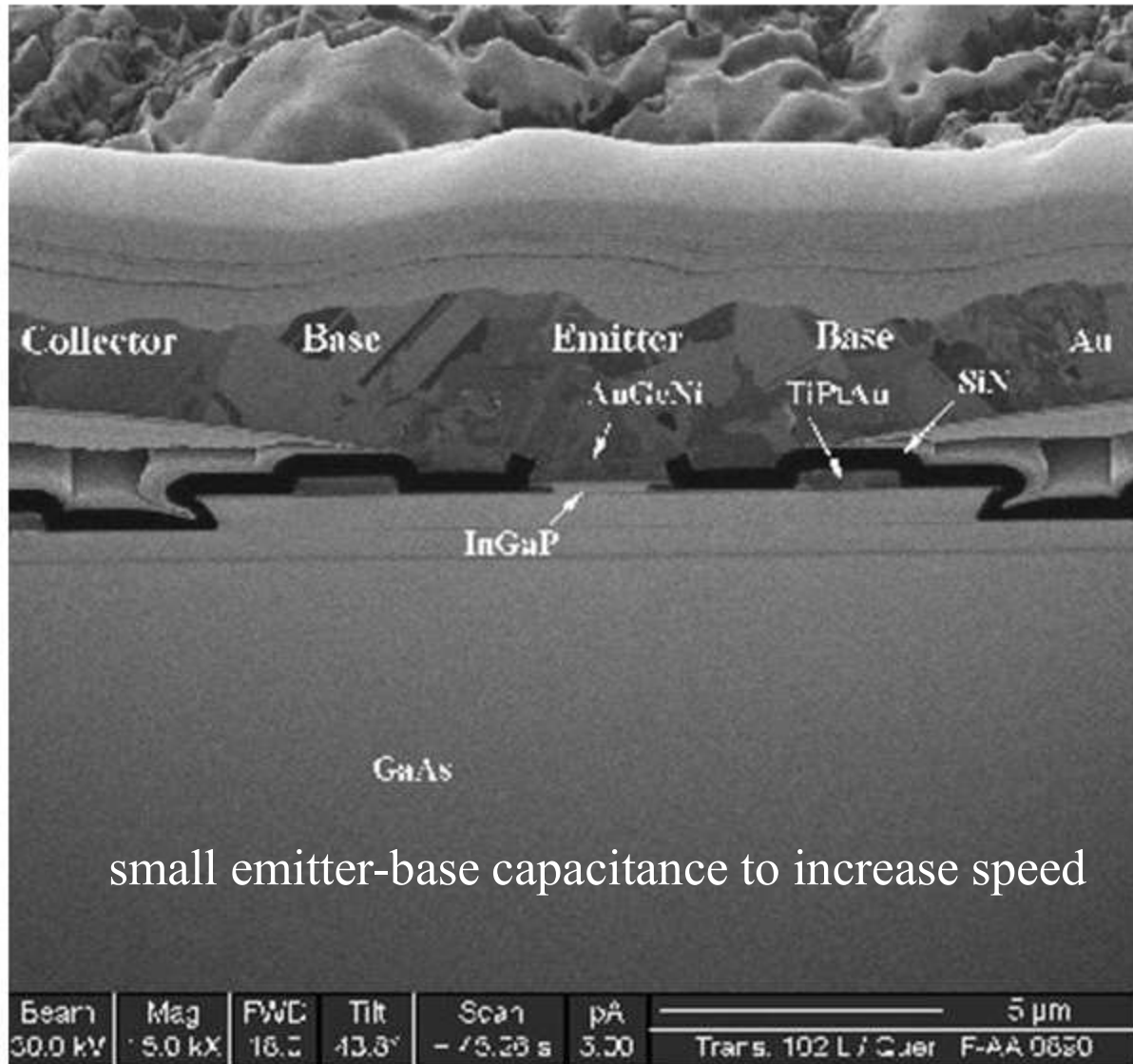


If the p-concentration in the channel is low, electrons emitted into the channel by the forward biased junction diffuse across the channel without recombining.

Heterojunction bipolar transistors



Heterojunction bipolar transistor



HBT current gain

$$I_C = \beta I_B$$

$$\beta = \frac{\alpha}{1 - \alpha} \approx \frac{n_{B0}}{p_{E0}} \quad (\text{npn})$$

Higher doping in the emitter makes the minority carrier concentration lower in the emitter.

$$n_{B0} = \frac{n_i^2}{N_A} = \frac{N_C N_V \exp(-E_{gB} / k_B T)}{N_A}$$
$$p_{E0} = \frac{n_i^2}{N_D} = \frac{N'_C N'_V \exp(-E_{gE} / k_B T)}{N_D}$$

If the emitter and the base have different band gaps

$$\beta = \frac{N_E}{N_B} \frac{N_C N_V}{N'_C N'_V} \exp\left(\frac{\Delta E_g}{k_B T}\right) \sim 100000$$

HBT current gain

A HBT has an emitter bandgap of 1.62 and a base bandgap of 1.42.

A BJT has an emitter bandgap of 1.42 and a base bandgap of 1.42.

Both have an emitter doping of 10^{18} cm^{-3} and a base doping of 10^{15} cm^{-3} .

How much larger is the gain in the HBT?

$$\frac{\beta(\text{HBT})}{\beta(\text{BJT})} = \exp\left(\frac{\Delta E_g}{k_B T}\right) = \exp\left(\frac{1.62 - 1.42}{0.0259}\right) = 2257$$

HBT

Trade off gain for higher speed

Higher base doping

- lower base resistance

- reduced Early effect

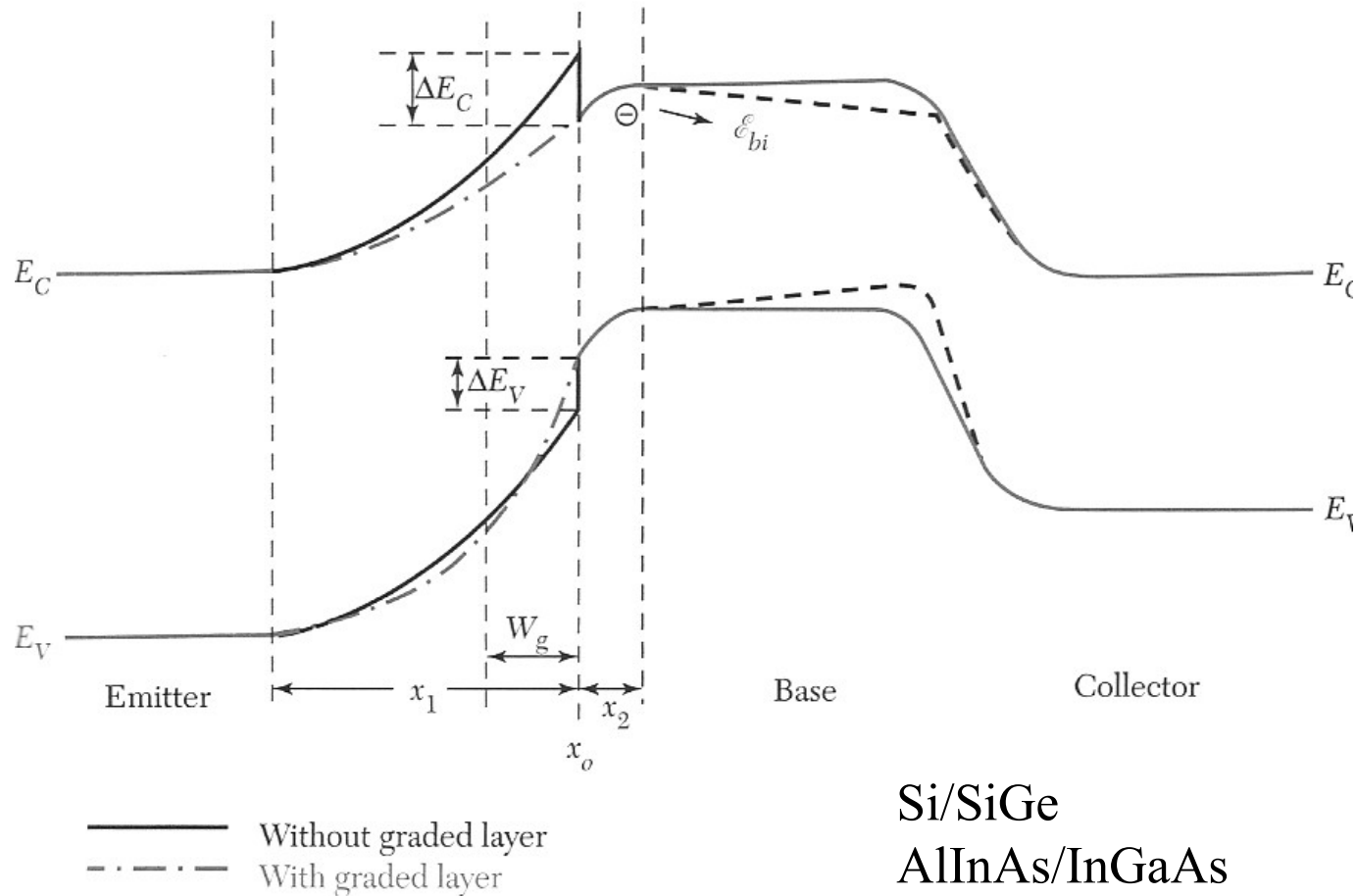
- less trouble with punch through

- base can be made thinner -> faster transistors

Because of higher base doping, a higher collector doping is possible without punch through

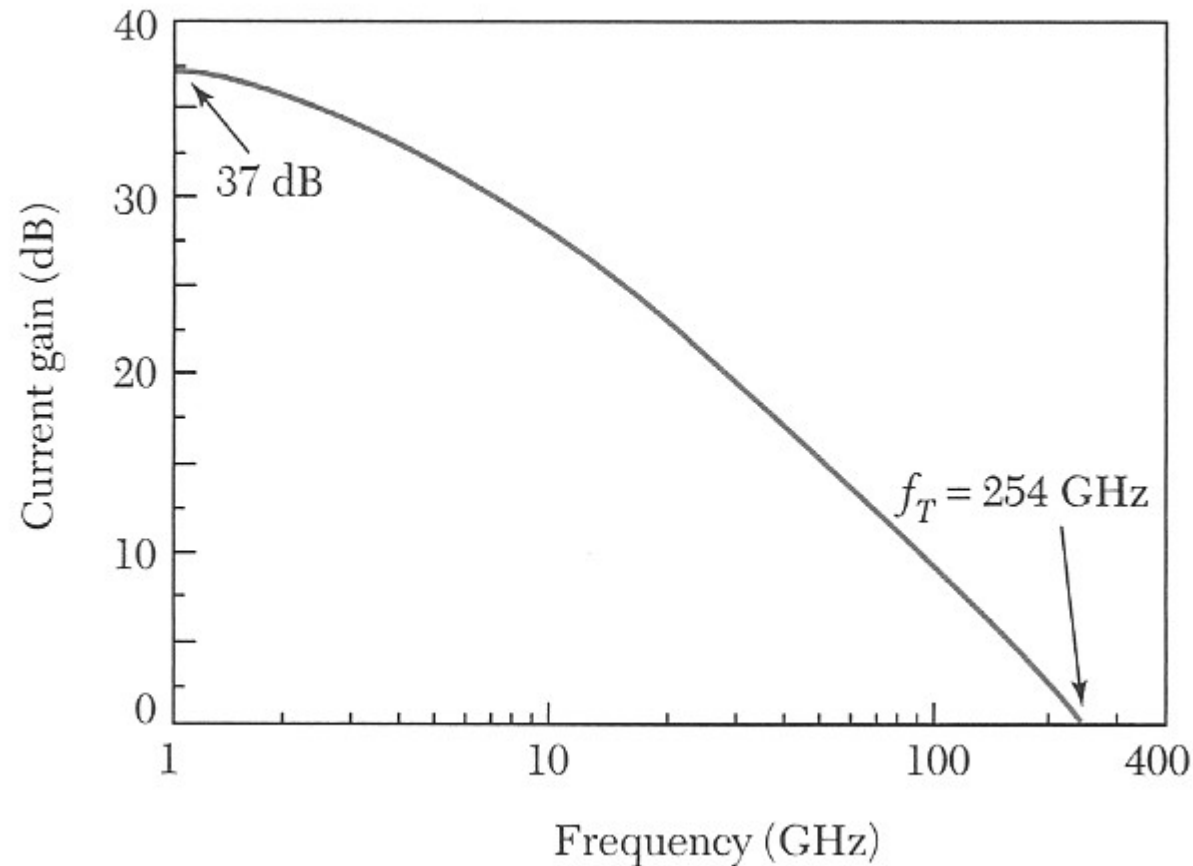
- lower collector resistance

HBT current gain



band discontinuity reduces emitter efficiency
Graded layer emitter and base improve performance

Heterojunction bipolar transistors



Fastest InP/InGaAs HBT's have an f_T of 710 GHz.

Higher doping in the base allows for a thinner base without punch through and lower base resistance and thus higher frequency operation

Microwave engineering

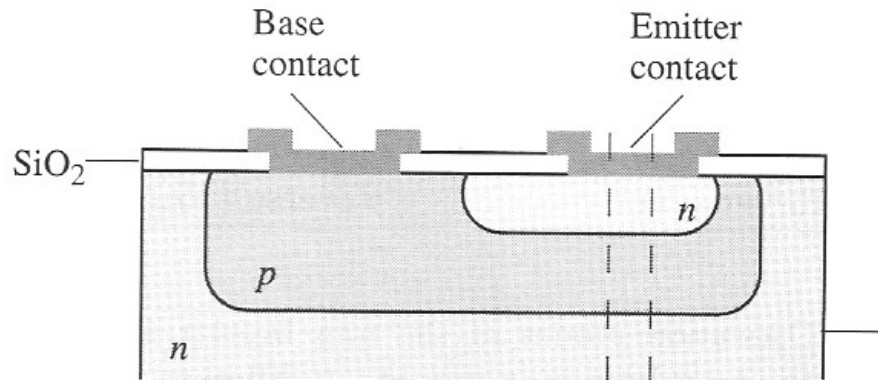
Electronics: $L \ll \lambda$ $f < \sim 10$ GHz

Microwave: $\lambda < L$ 10 GHz $< f < 1$ THz

TeraHertz: $\lambda \ll L$ 1 THz $< f < 100$ THz

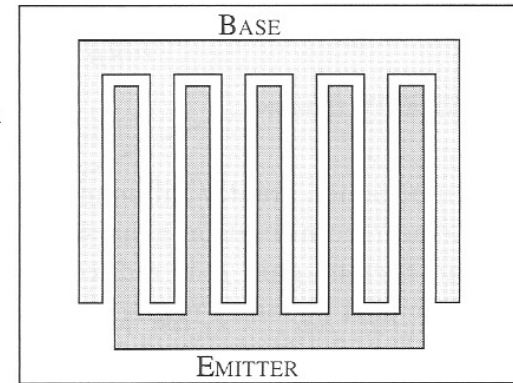
Optics: $\lambda \ll L$ 100 THz

Interdigitated contacts in power transistors

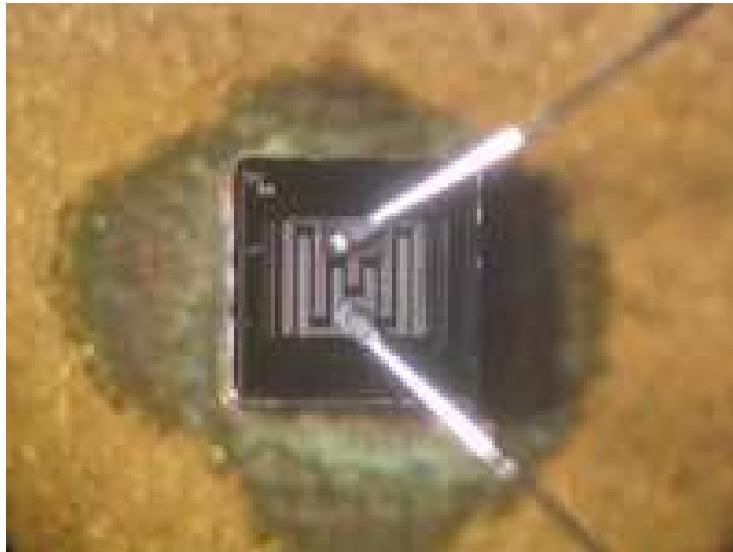
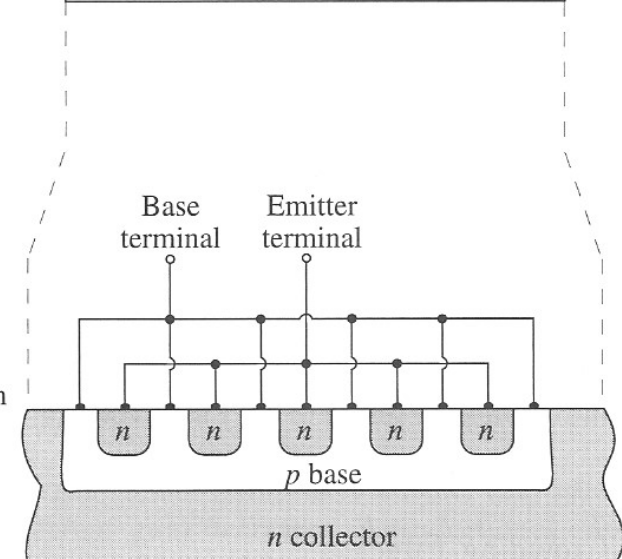


Interdigitated fingers to inject current uniformly into a bipolar device

Top view

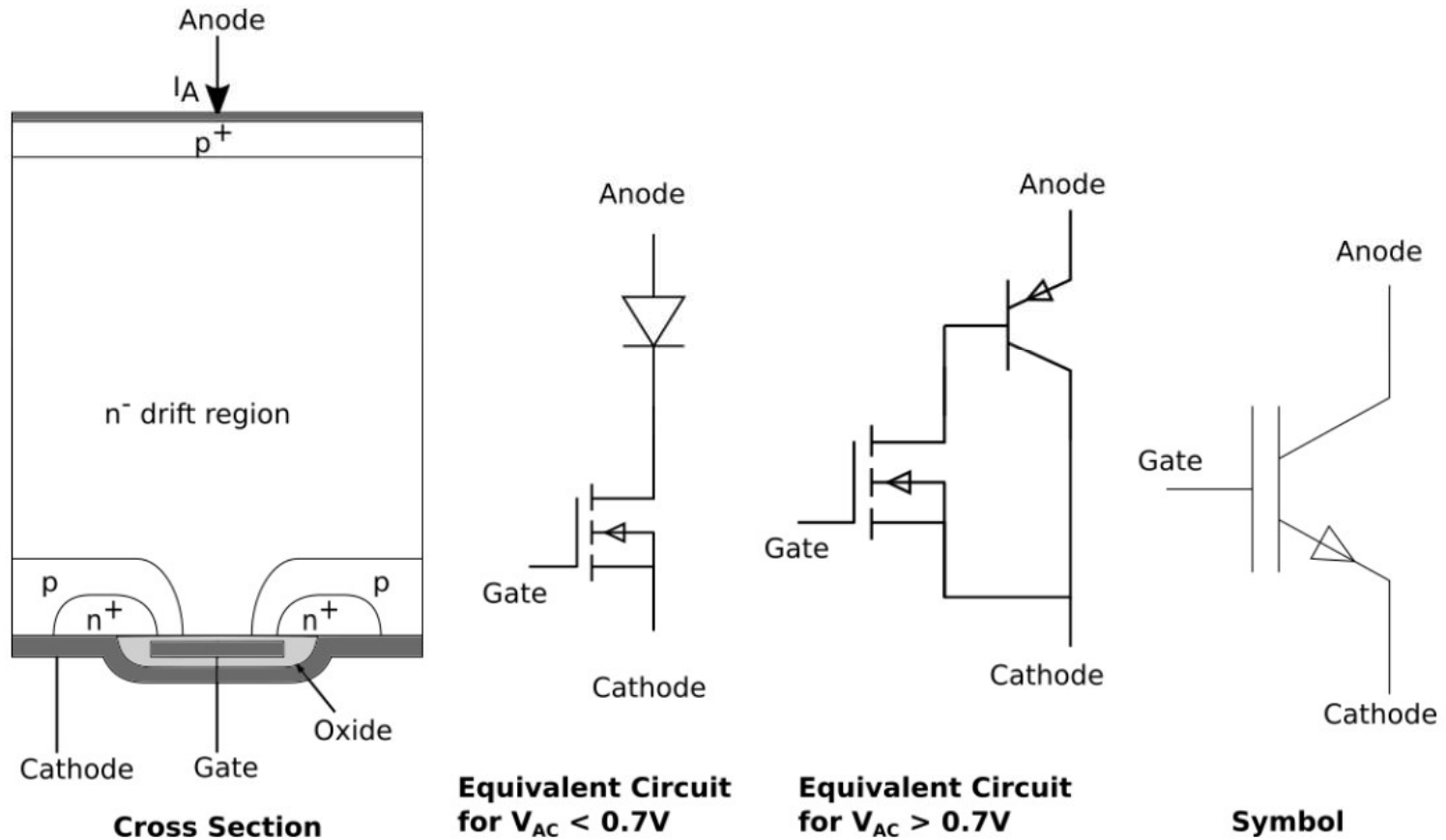


Cross-section



IGBT - Insulated Gate Bipolar Transistor

An IGBT is a combination of an insulated gate FET and a bipolar transistor. It is primarily used for switching high power loads



Used to switch large currents (in electric cars or trains).

<http://lampx.tugraz.at/~hadley/psd/L13/igbt.html>